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P. Leader	Check by	Design by

PCB P/N: 1P-106A100-40SB

Project Code & Schematics Subject: MS80 Main Board

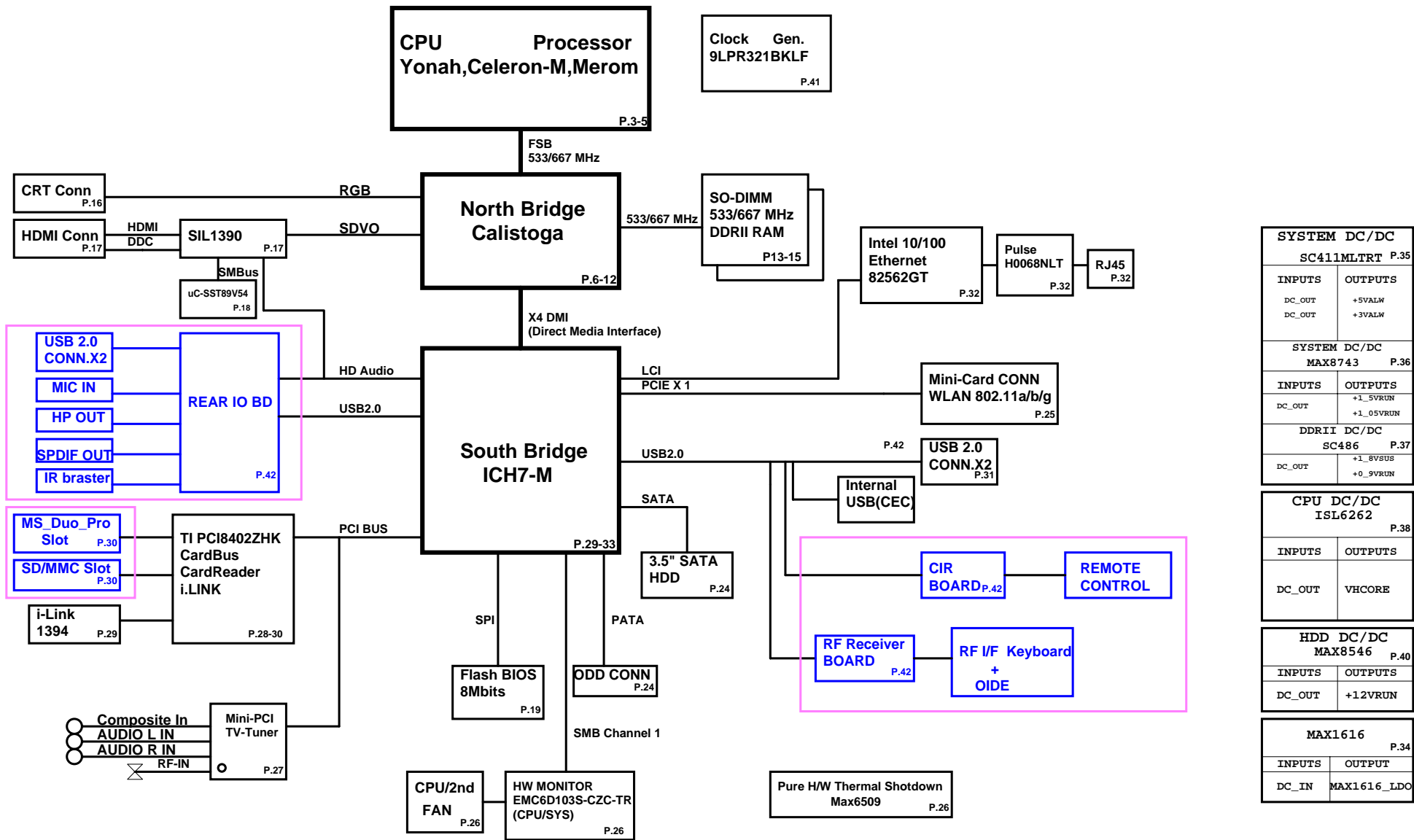
FOXCONN HON HAI PRECISION IND. CO., LTD.
CPBG - R&D Division

Title: **Index Page**

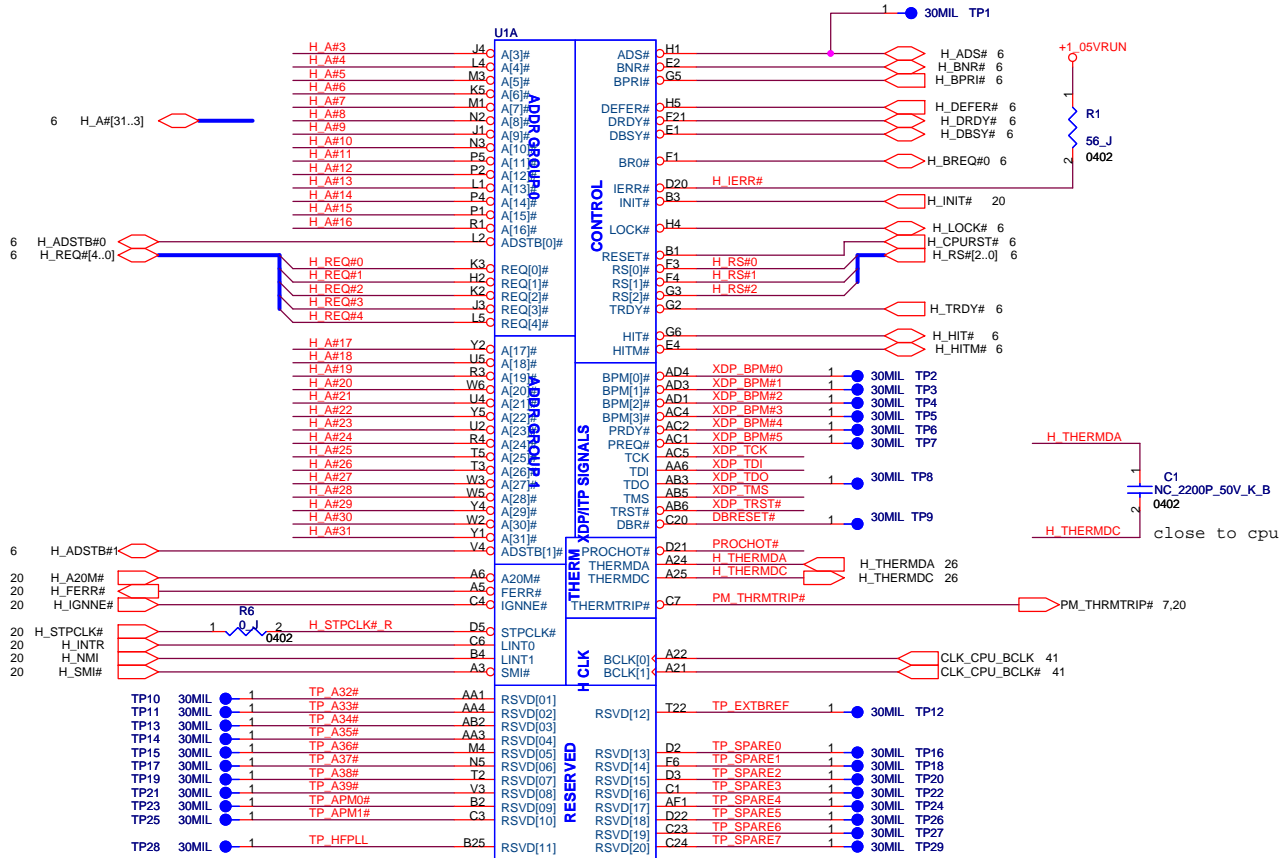
Size: Custom Document Number: **MS80-1-04** Rev: 0.1

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MS80 Bolck diagram



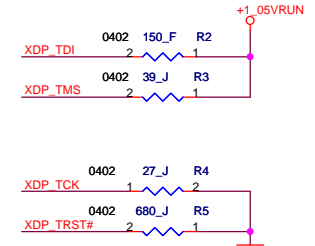
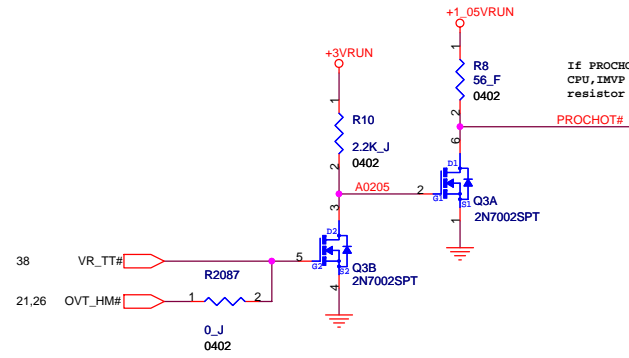
SYSTEM DC/DC	
SC411MLTRT P.35	
INPUTS	OUTPUTS
DC_OUT	+5VALW
DC_OUT	+3VALW
SYSTEM DC/DC	
MAX8743 P.36	
INPUTS	OUTPUTS
DC_OUT	+1_5VRUN
	+1_05VRUN
DDRII DC/DC	
SC486 P.37	
DC_OUT	+1_8VSUS
	+0_9VRUN
CPU DC/DC	
ISL6262 P.38	
INPUTS	OUTPUTS
DC_OUT	VHORE
HDD DC/DC	
MAX8546 P.40	
INPUTS	OUTPUTS
DC_OUT	+12VRUN
MAX1616	
P.34	
INPUTS	OUTPUT
DC_IN	MAX1616_LDO



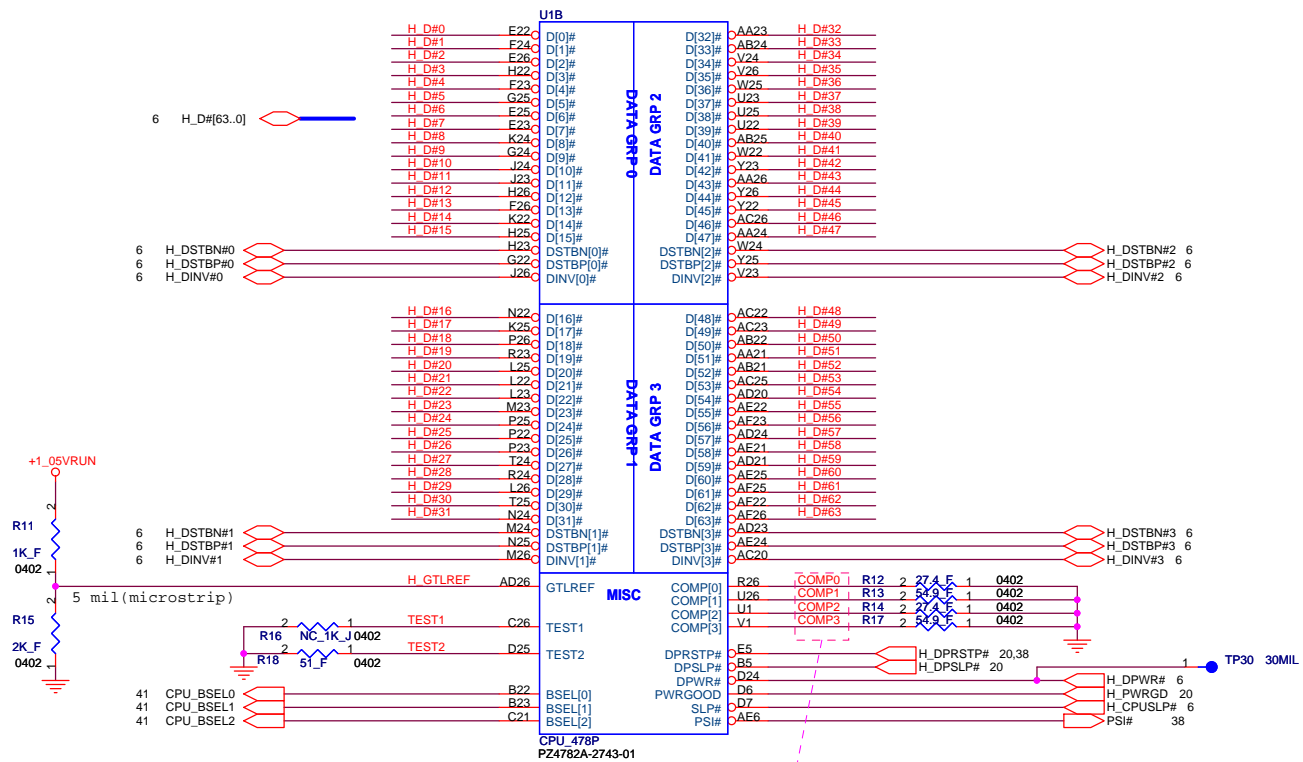
Layout note:
no stub on
H_STPCLK#

A#[32-39], APM#[0-1]:
Leave escape routing
on for future
functionality

ICH7M's GPIO12: VIL----> -0.5V ~ 0.8V
VIH----> 2.0V ~ 3.3+0.5V
YONAH's PROCHOT#: VIL----> -0.1V ~ 0.3*VCCP
VIH----> 0.7*VCCP ~ VCCP+0.1



Debug port not used.
resistors close to CPU.



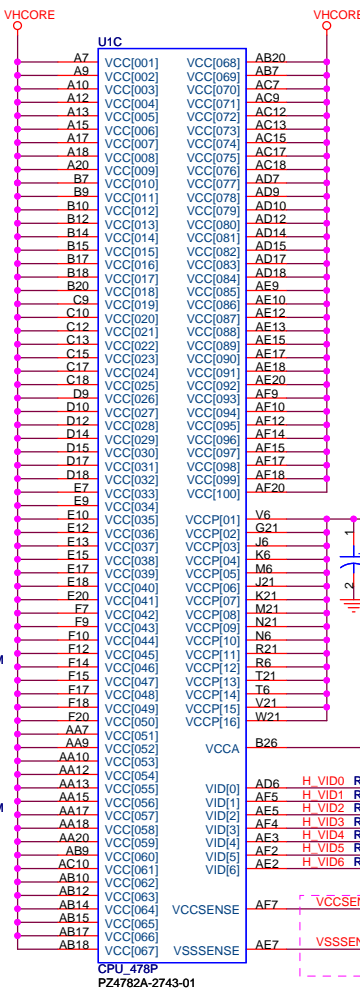
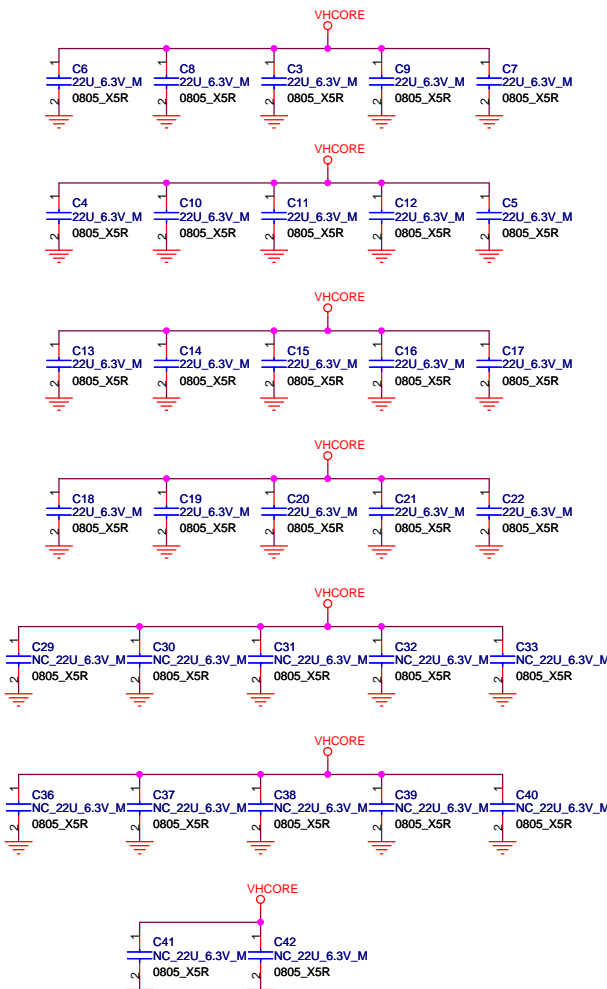
Place close to CPU

Layout Note:
Z0=55 ohm, 0.5"
max for GTLREF.

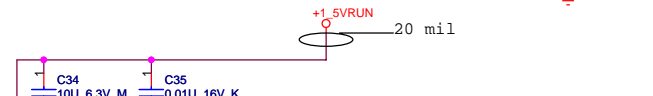
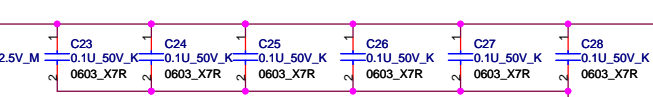
FSB Frequency Table:

BSEL[2:0]	Freq.(MHz)
LLL	Reserve
LLH	133
LHL	Reserve
LHH	166

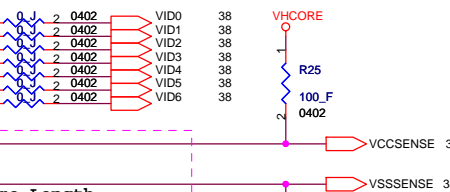
Layout Note:
Comp0,2 connect with Z0=27.4 ohm, make trace length shorter then 0.5".
Comp1,3 connect with Z0=55 ohm, make trace length shorter then 0.5".



CPU_VCCA----->130mA
 CPU_VCCP----->2.5A
 CPU_VCC----->36A

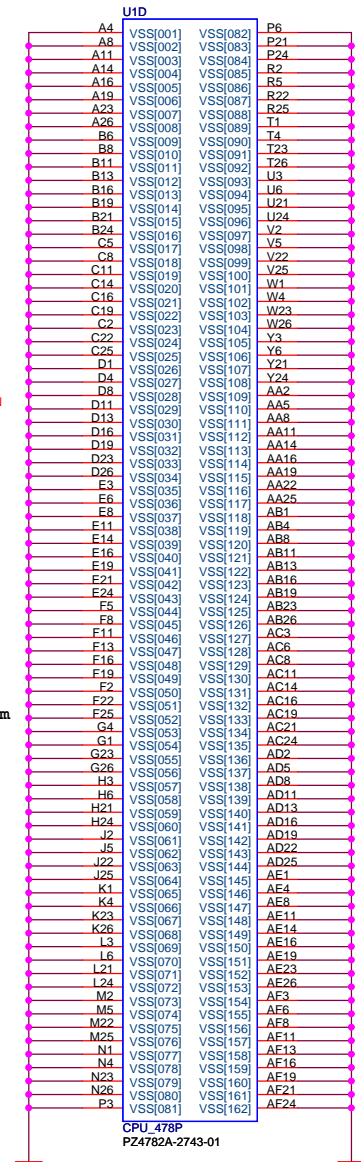


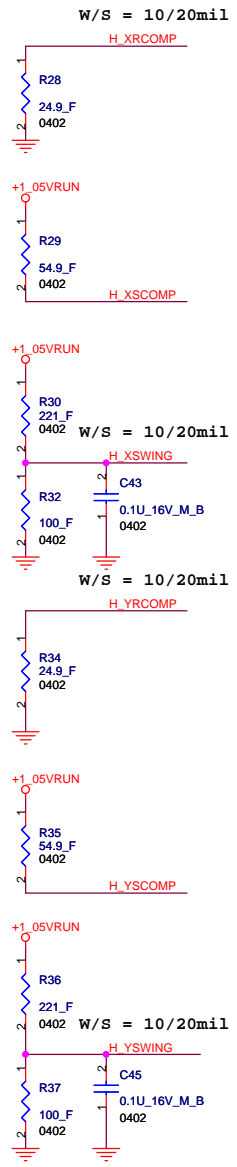
maximum current is 130mA for CPU_VCCA in Merom
 and 600A/us slew rate for CPU_VCCA



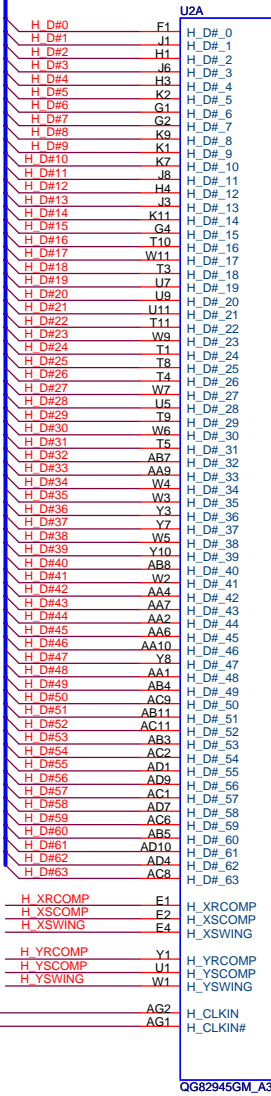
Layout Note: Route VCCSENSE traces at 27.4 Ohms with 50 mil spacing. Place PU and PD within 1 inch of cpu.
 width=18 mil
 spacing=7 mil

CRB :
 add 12 dummy caps
 0825

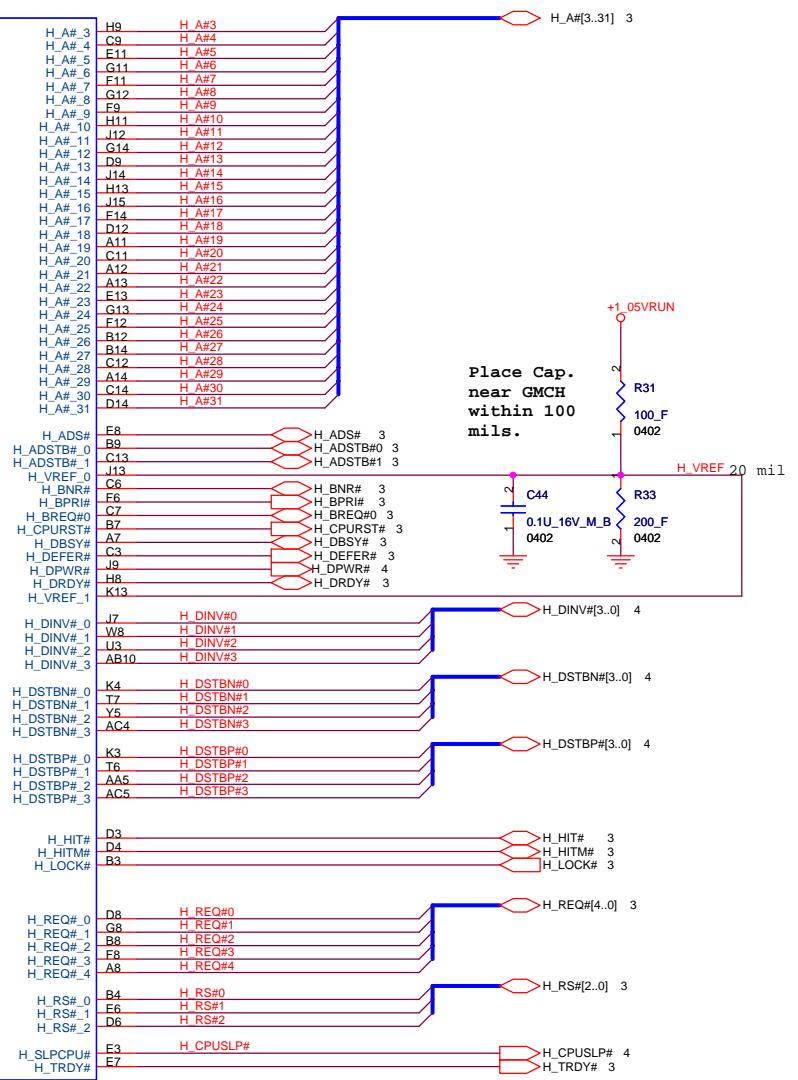


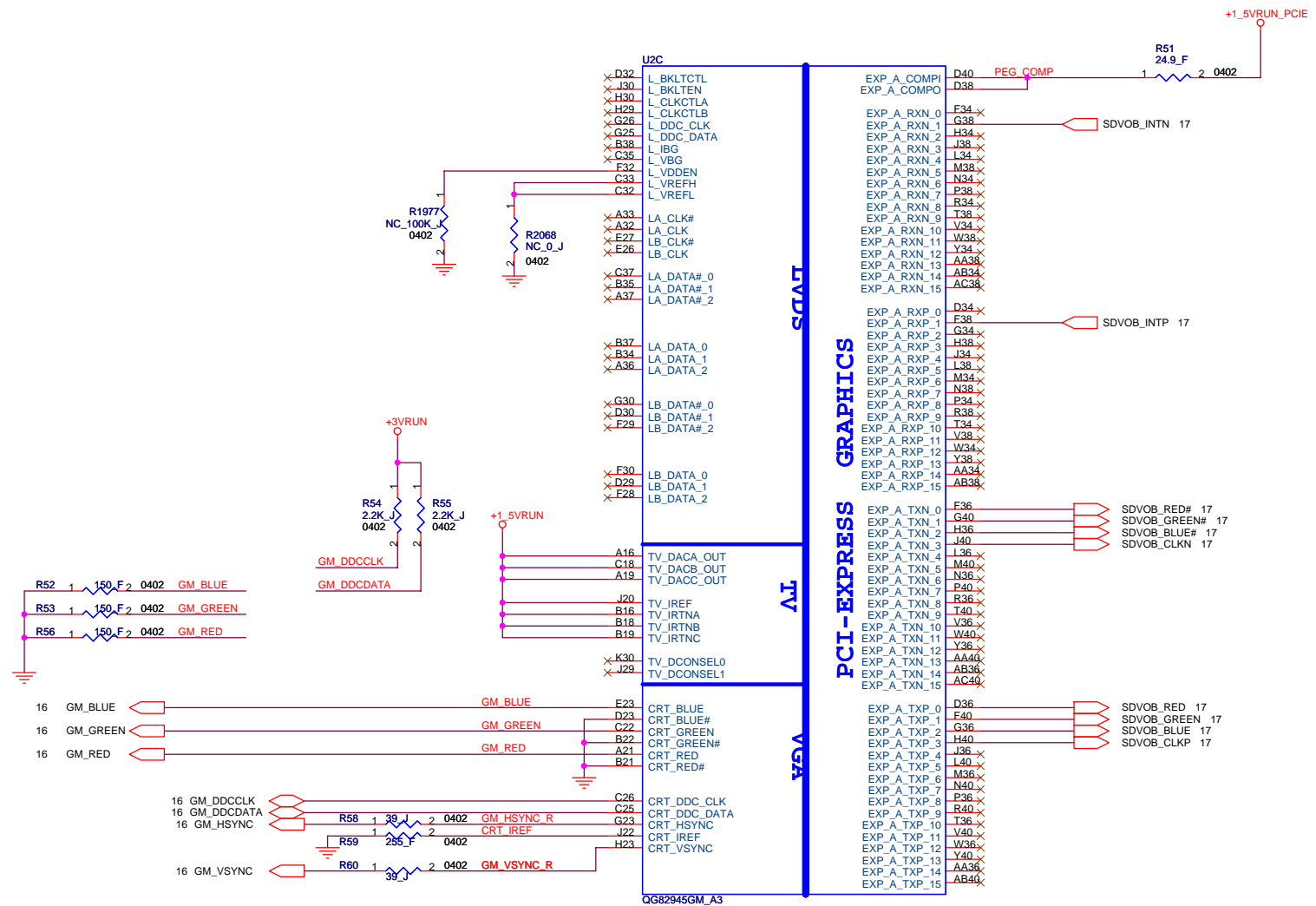


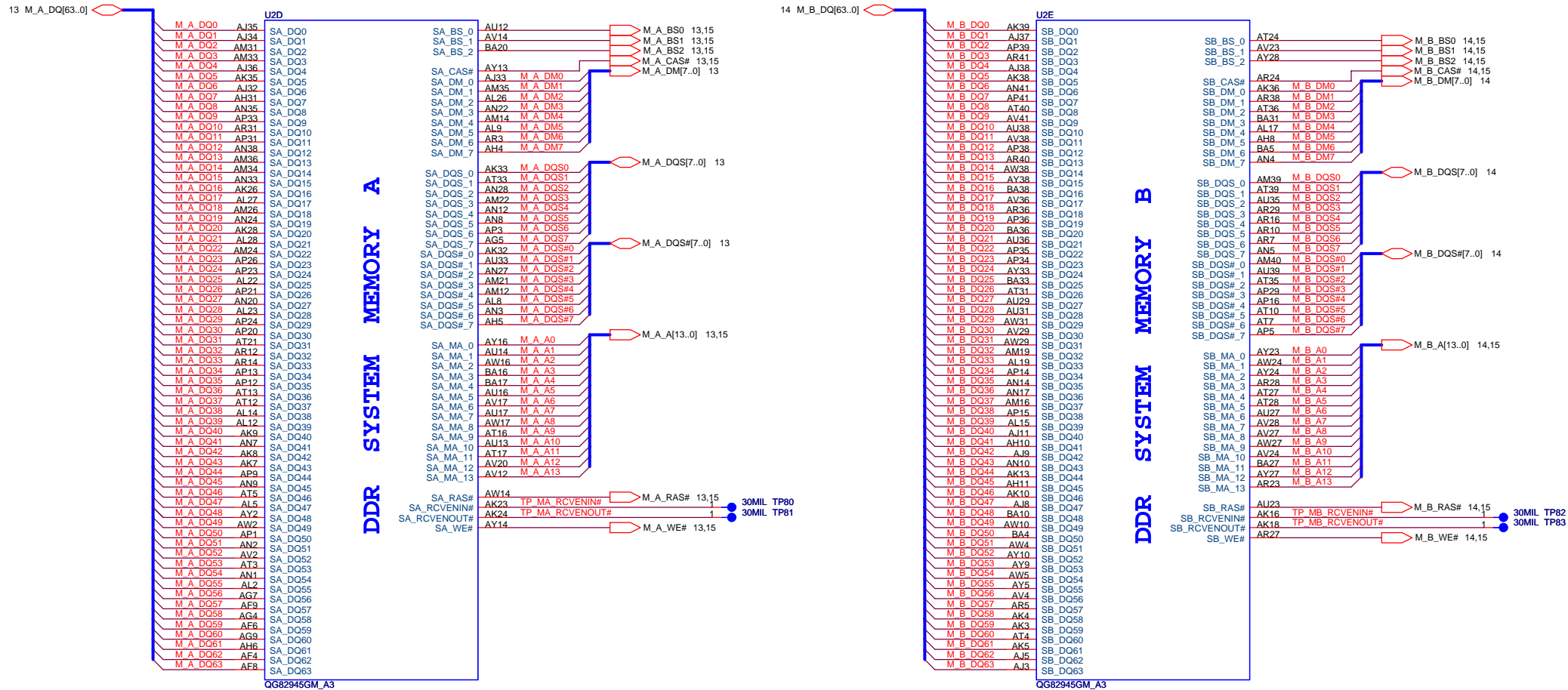
4 H_D#[63..0] H_D#[63..0]



HOST





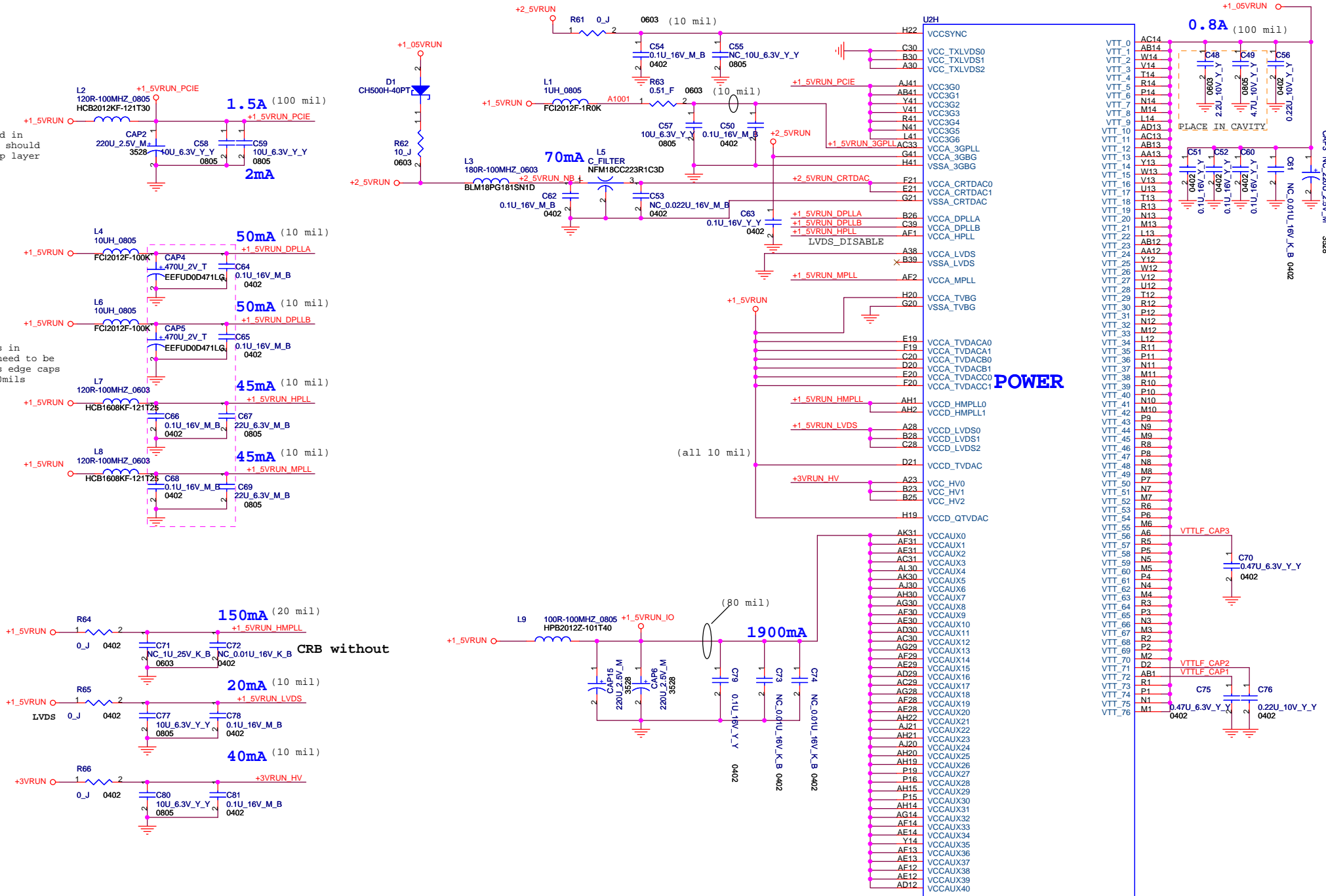


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QG82945GM_A3

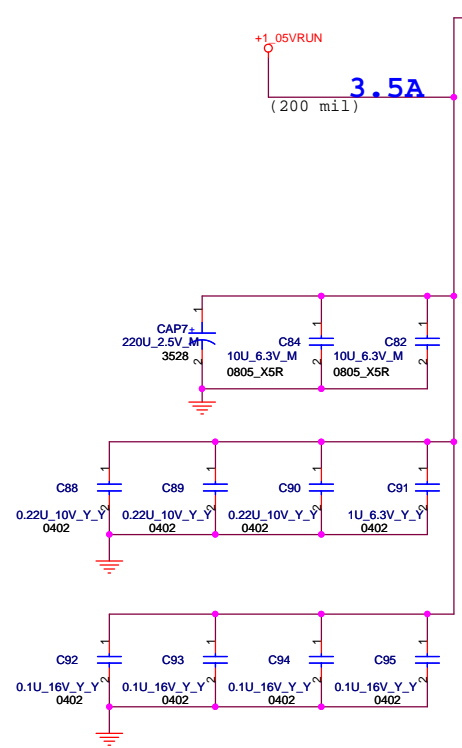
Caps used in +1.5VSRUN should be on top layer

NOTE:
0.1uF caps in 1.5SxPLL need to be located as edge caps within 200mils

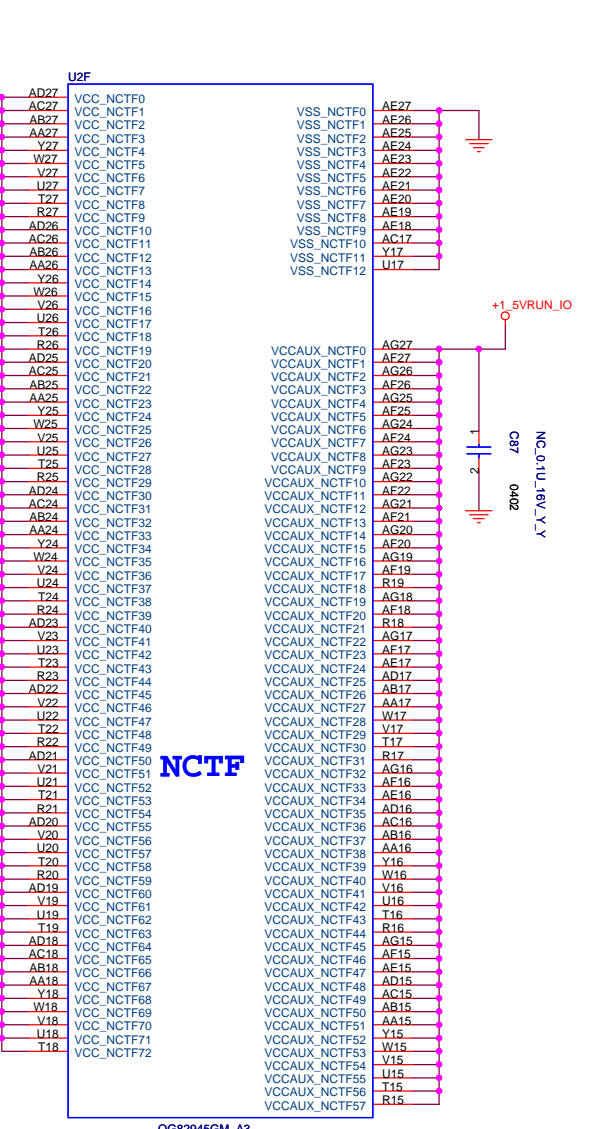
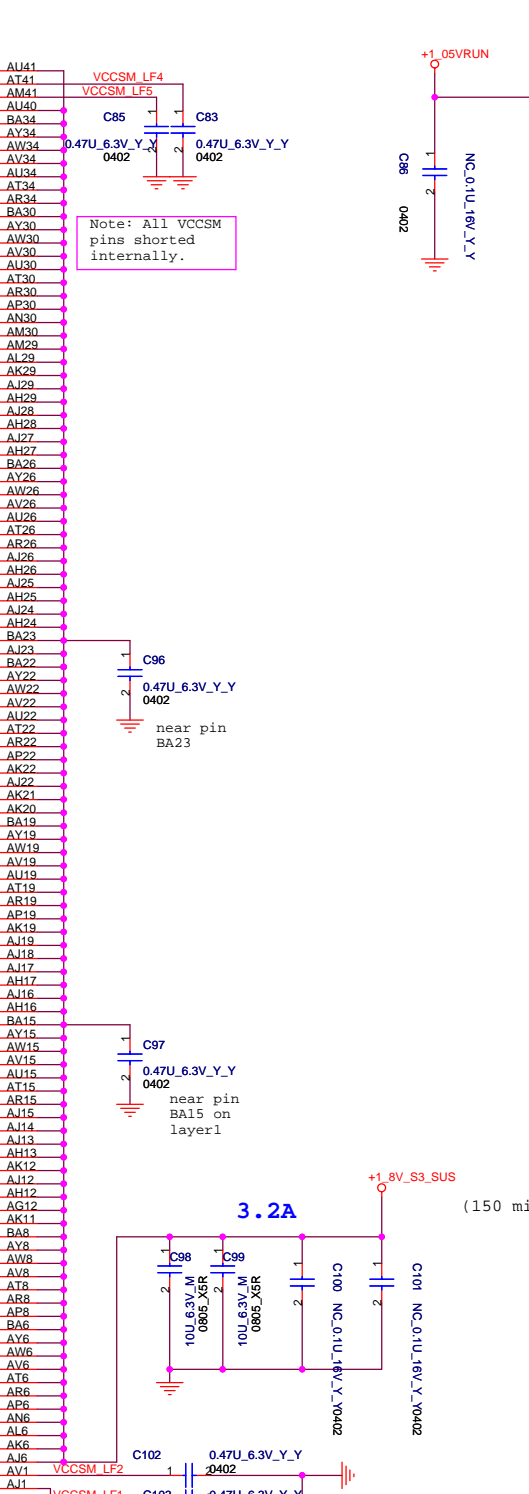


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FOXCONN		HON HAI PRECISION IND. CO., LTD.	
Title		CPBG - R&D Division	
CALISTOGA(POWER,VCC) 5 of 7			
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AA33	VCC_0
W33	VCC_1
P33	VCC_2
N33	VCC_3
L33	VCC_4
J33	VCC_5
AA32	VCC_6
Y32	VCC_7
W32	VCC_8
V32	VCC_9
P32	VCC_10
N32	VCC_11
M32	VCC_12
L32	VCC_13
J32	VCC_14
AA31	VCC_15
W31	VCC_16
V31	VCC_17
T31	VCC_18
R31	VCC_19
P31	VCC_20
N31	VCC_21
M31	VCC_22
AA30	VCC_23
Y30	VCC_24
W30	VCC_25
U30	VCC_26
T30	VCC_27
R30	VCC_28
P30	VCC_29
N30	VCC_30
M30	VCC_31
L30	VCC_32
AA29	VCC_33
Y29	VCC_34
W29	VCC_35
V29	VCC_36
P29	VCC_37
N29	VCC_38
M29	VCC_39
L29	VCC_40
AA28	VCC_41
Y28	VCC_42
W28	VCC_43
V28	VCC_44
P28	VCC_45
N28	VCC_46
M28	VCC_47
L28	VCC_48
AA27	VCC_49
Y27	VCC_50
W27	VCC_51
V27	VCC_52
P27	VCC_53
N27	VCC_54
M27	VCC_55
L27	VCC_56
P26	VCC_57
N26	VCC_58
L26	VCC_59
N25	VCC_60
M25	VCC_61
L25	VCC_62
P24	VCC_63
N24	VCC_64
M24	VCC_65
AA23	VCC_66
Y23	VCC_67
W23	VCC_68
P23	VCC_69
N23	VCC_70
M23	VCC_71
L23	VCC_72
AA22	VCC_73
Y22	VCC_74
W22	VCC_75
P22	VCC_76
N22	VCC_77
M22	VCC_78
L22	VCC_79
AA21	VCC_80
Y21	VCC_81
W21	VCC_82
N21	VCC_83
M21	VCC_84
L21	VCC_85
AA20	VCC_86
Y20	VCC_87
W20	VCC_88
P20	VCC_89
N20	VCC_90
M20	VCC_91
L20	VCC_92
AA19	VCC_93
Y19	VCC_94
W19	VCC_95
P19	VCC_96
N19	VCC_97
M19	VCC_98
L19	VCC_99
N18	VCC_100
M18	VCC_101
L18	VCC_102
P17	VCC_103
N17	VCC_104
M17	VCC_105
L17	VCC_106
M16	VCC_107
L16	VCC_108
	VCC_109
	VCC_110
	VCC_111



VCC

NCTF

QG82945GM_A3

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Title: **CALISTOGA(VCC CORE) 6 of 7**

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7 MCH_CFG_5 ← 1 ● 30MIL TP84

MCH_CFG_5 Low = DMiX2 High = DMiX4

7 MCH_CFG_6 ← 1 ● 30MIL TP85

MCH_CFG_6 Low = Moby Dick High = Calistoga DDR2 select (default high)

7 MCH_CFG_7 ← 1 ● 30MIL TP87

MCH_CFG_7 (CPU Strap) Low = RSVd High = Mobile Yonah processor

7 MCH_CFG_9 ← 1 ● 30MIL TP89

MCH_CFG_9 (PCIe Graphics Lane) Low = Reverse Lane High = Normal operation

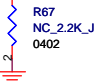
For layout convenience

7 MCH_CFG_10 ← 1 ● 30MIL TP90

MCH_CFG_10 (HOST PLL VCC_SELECT) Low = RESERVED High = MOBILITY

7 MCH_CFG_11 ← 1 ● 30MIL TP91

MCH_CFG_11 (PSB 4x CLK ENABLE) Low = Reserved High = Calistoga



7 MCH_CFG_12 ← 1 ● 30MIL TP92

7 MCH_CFG_13 ← 1 ● 30MIL TP93

MCH_CFG_[13:12] (XOR/ALLZ) 00=Partial Clock Gating Disable 01=XOR Mode Enable 10=All-Z Mode Enable 11=Normal Operation(Default)

7 MCH_CFG_16 ← 1 ● 30MIL TP94

MCH_CFG_16 (FSB Dynamic ODT) Low = Dynamic ODT Disabled High = Dynamic ODT Enable

MCH_CFG_18 (VCC_CORE Select) Low = 1.05V(default) High = 1.5V

7 MCH_CFG_18 ← 1 ● 30MIL TP86

MCH_CFG_19 (DMI LANE REVERSAL) Low = Normal(default) High = LANES REVERSED

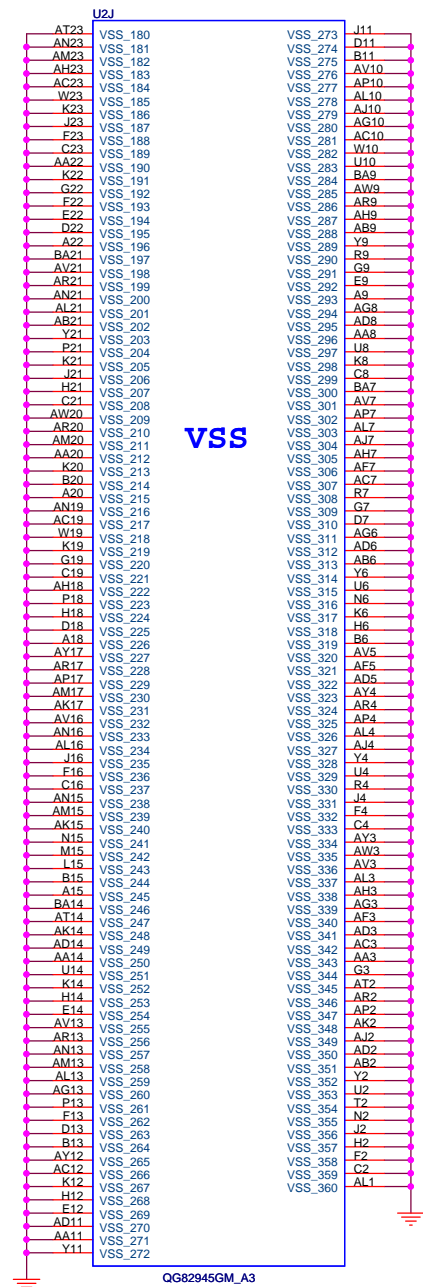
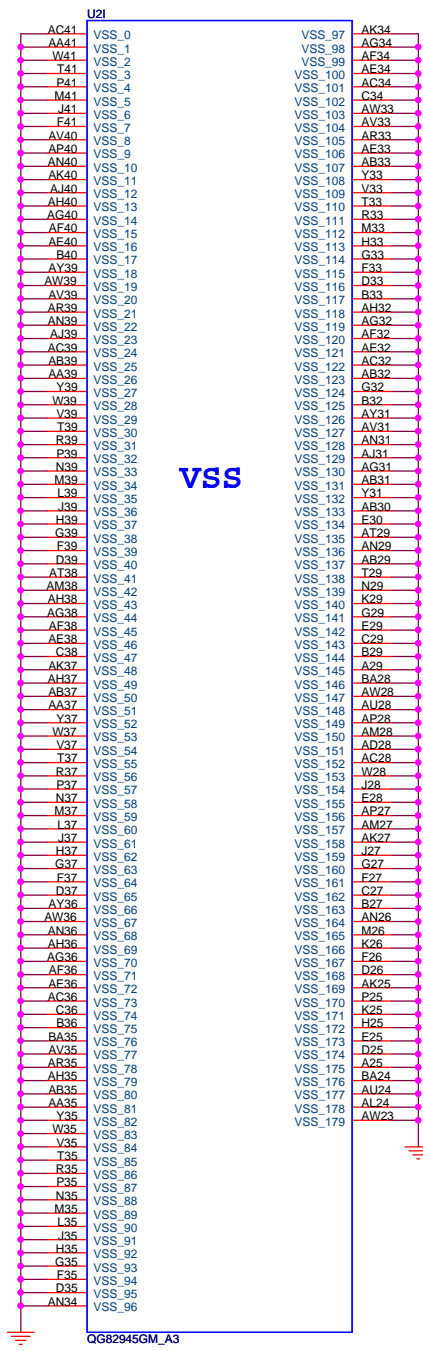
7 MCH_CFG_19 ← 1 ● 30MIL TP88

MCH_CFG_20 (PCIe Backward Interoperability mode) Low = Only SDVO or PCIe x1 is operational (defaults) High = SDVO and PCIe x1 are operating simultaneously via the PEG port

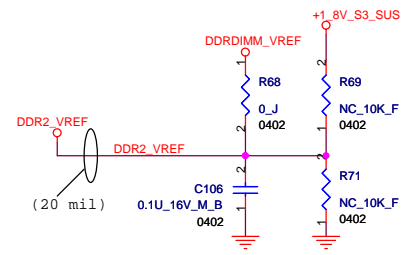
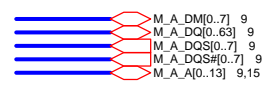
7 MCH_CFG_20 ← 1 ● 30MIL TP91

Layout Noe: Location of all MCH_CFG strap resistors needs to be close to trace to minimize stub

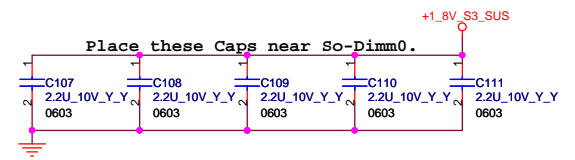
Check CALISTOGA version , after A2 version , if systec can't boot up then NC the pull low R



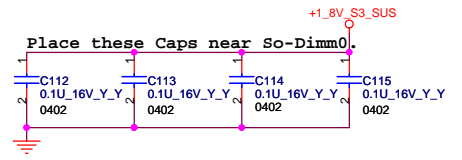
1.8V per DIMM=3.08A



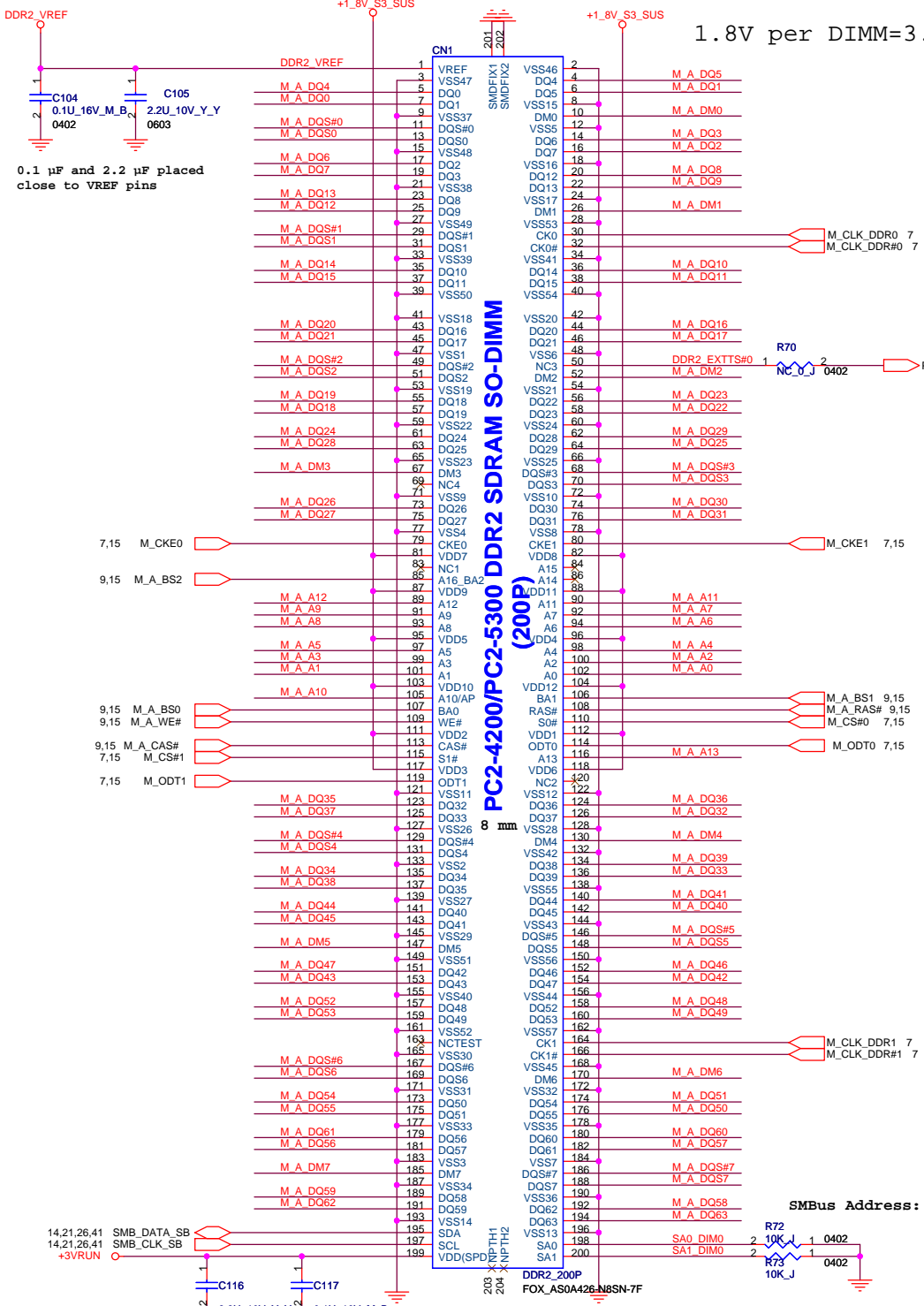
Close to DIMM



Place these Caps near So-Dimm0.



Place these Caps near So-Dimm0.

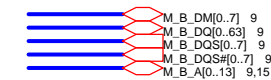
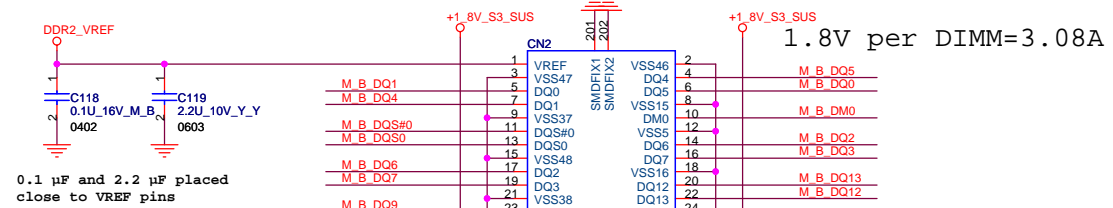


PC2-4200/PC2-5300 DDR2 SDRAM SO-DIMM (200P)

DIMM_0

SMBus Address: A0(W)/A1(R)

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CPBG - R&D Division		
Title: DDR(I)SO-DIMM_0		
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0.1 uF and 2.2 uF placed close to VREF pins

1.8V per DIMM=3.08A

7,15 M_CKE2

9,15 M_B_BS2

9,15 M_B_BS0

9,15 M_B_WE#

9,15 M_B_CAS#

7,15 M_CS#3

7,15 M_ODT3

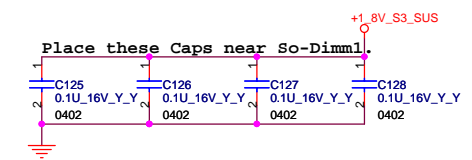
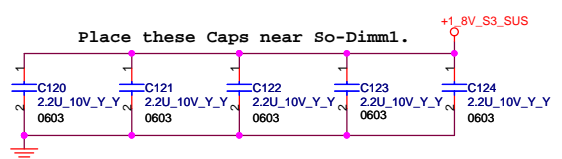
+3VRUN

13,21,26,41 SMB_DATA_SB

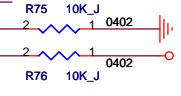
13,21,26,41 SMB_CLK_SB

PC2-4200/PC2-5300 DDR2 SDRAM SO-DIMM (200P)

4 mm



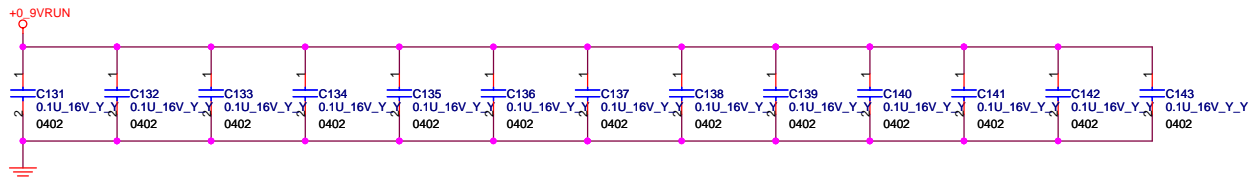
SMBus Address: A4(W)/A5(R)



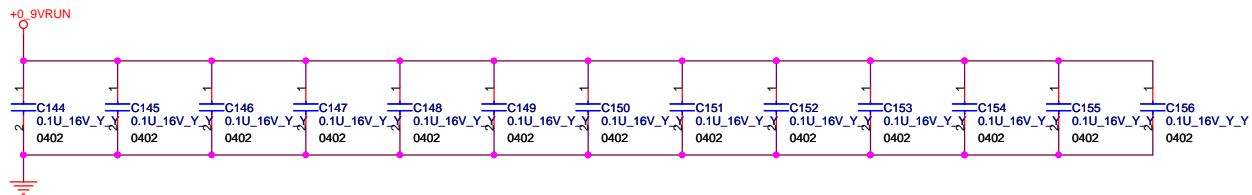
203 X NPTH1
204 X NPTH2
DDR2_200P
FOX_AS0A426-14SN-7F

DIMM_1

FOXCONN		HON HAI PRECISION IND. CO., LTD.	
		CPBG - R&D Division	
Title DDR(I)SO-DIMM_1			
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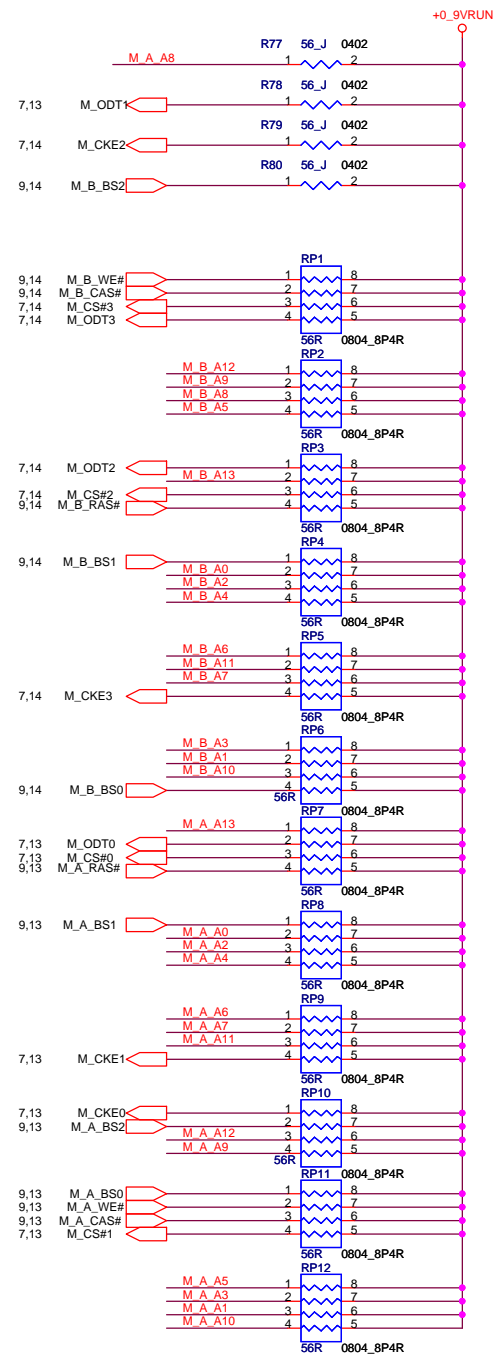
Layout note: Place 1 cap close to every 1 R-pack terminated to +0_9VRUN

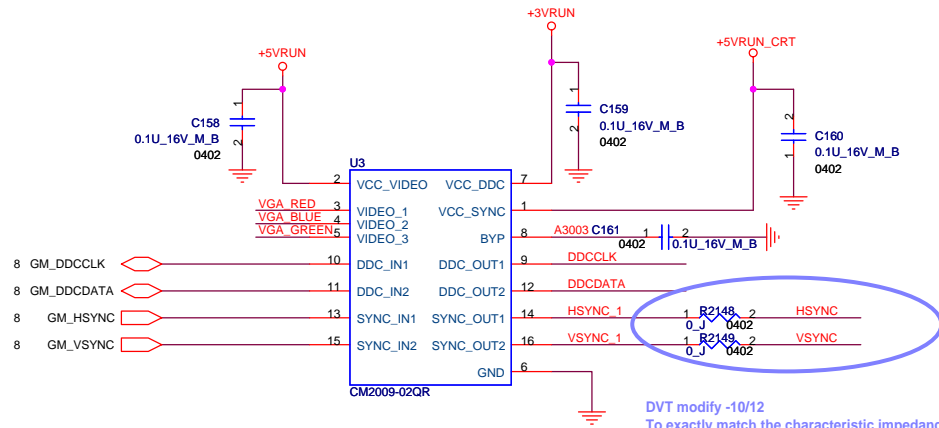


Layout note: Place 1 cap close to every 1 R-pack terminated to +0_9VRUN

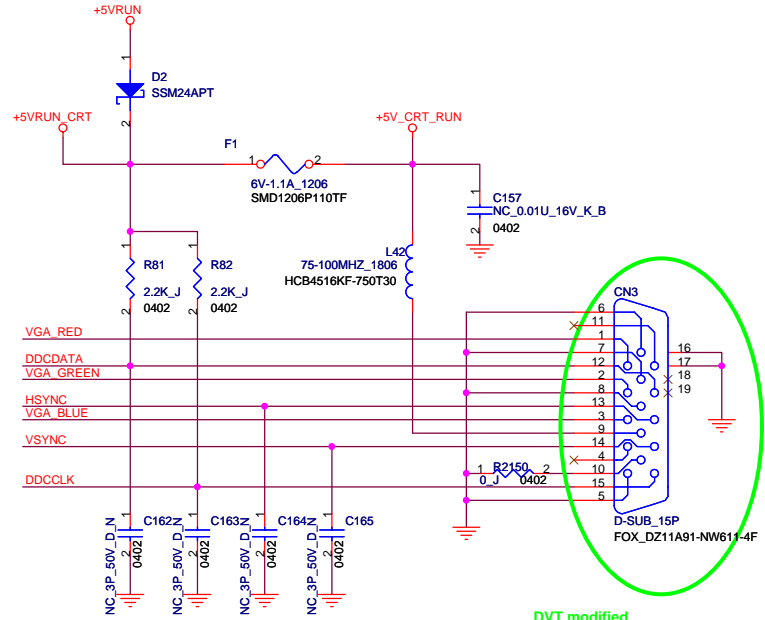
9.13 M_A_A[0.13]

9.14 M_B_A[0.13]

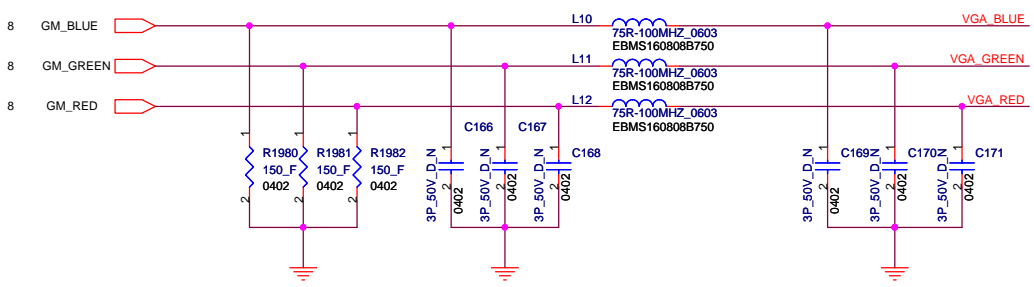


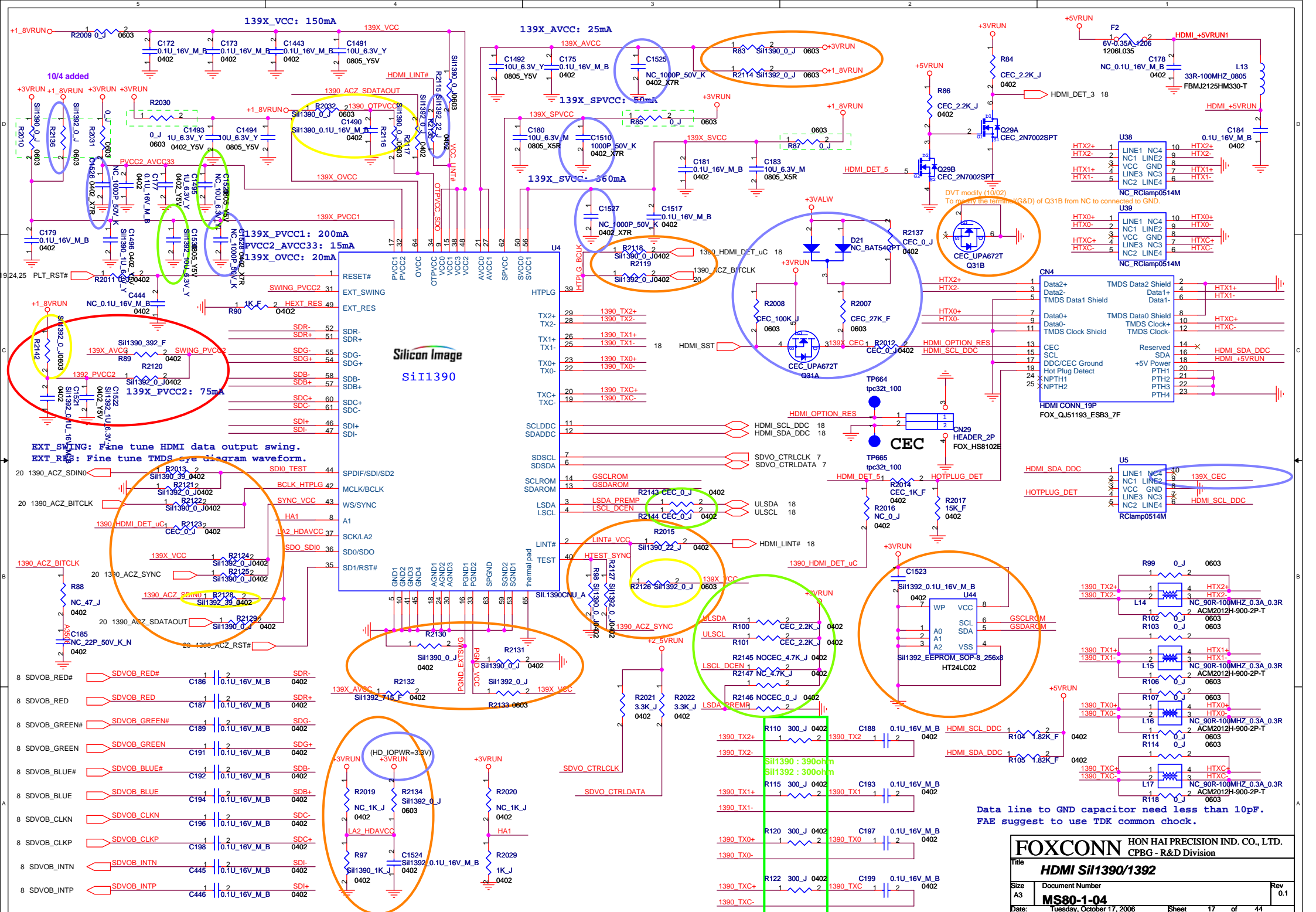


DVT modify -10/12
 To exactly match the characteristic impedance of the SYNC lines ,
 added this 2pcs series resistor for fine tune.



DVT modified
 Connector color changed
 Pin10 connected to GND for SONY SPEC

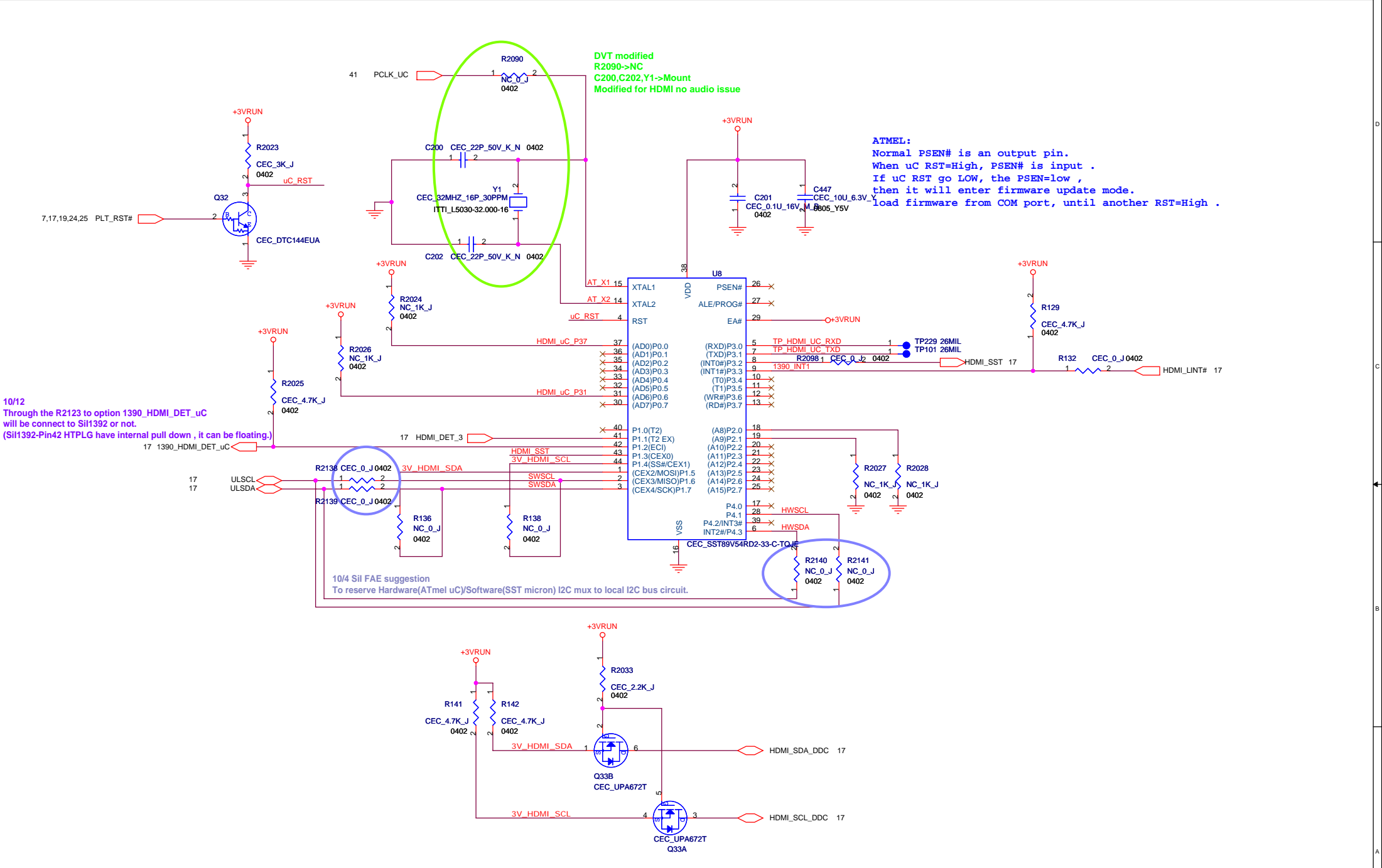




EXT_SWING: Fine tune HDMI data output swing.
 EXT_RES: Fine tune TMSD eye diagram waveform.

Data line to GND capacitor need less than 10pF.
 FAE suggest to use TDK common chock.

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Title HDMI Si11390/1392		
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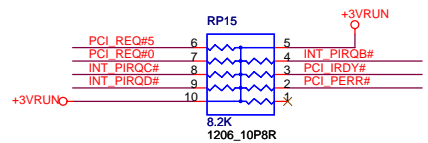
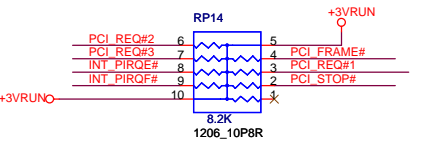
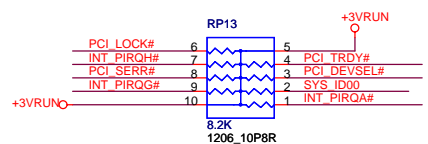


DVT modified
 R2090->NC
 C200,C202,Y1->Mount
 Modified for HDMI no audio issue

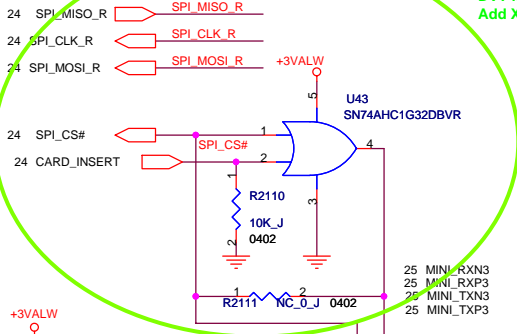
ATMEL:
 Normal PSEN# is an output pin.
 When uC RST=High, PSEN# is input .
 If uC RST go LOW, the PSEN=low ,
 then it will enter firmware update mode.
 load firmware from COM port, until another RST=High .

10/12
 Through the R2123 to option 1390_HDMI_DET_uC
 will be connect to Sii1392 or not.
 (Sii1392-Pin42 HTPLG have internal pull down , it can be floating.)

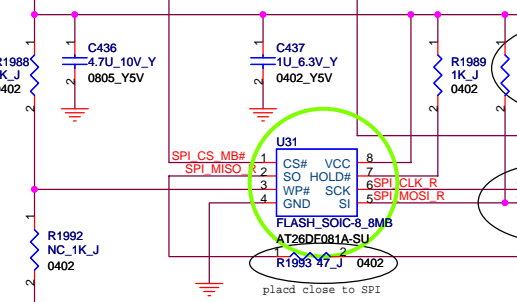
10/4 Sii FAE suggestion
 To reserve Hardware(ATmel uC)/Software(SST micron) I2C mux to local I2C bus circuit.



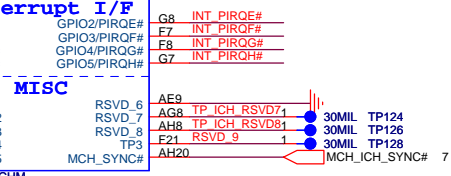
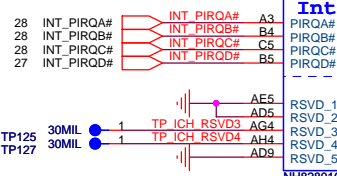
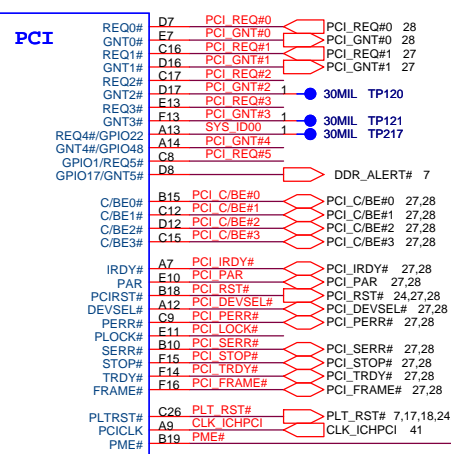
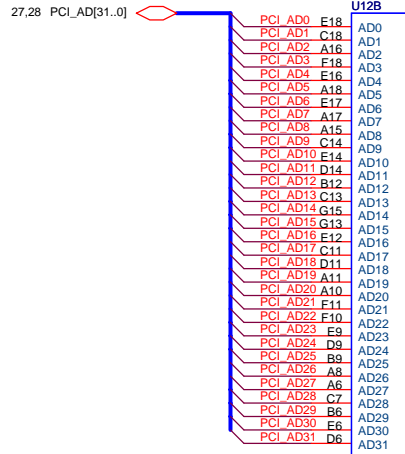
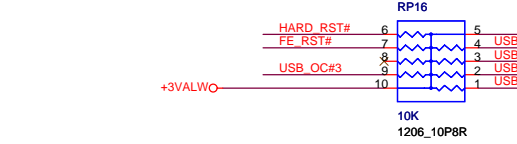
PCI Pullups



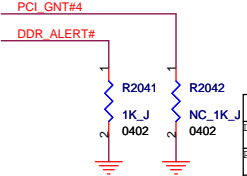
DVT modified
Add X-BUS function



DVT modified
Cancel BIOS socket



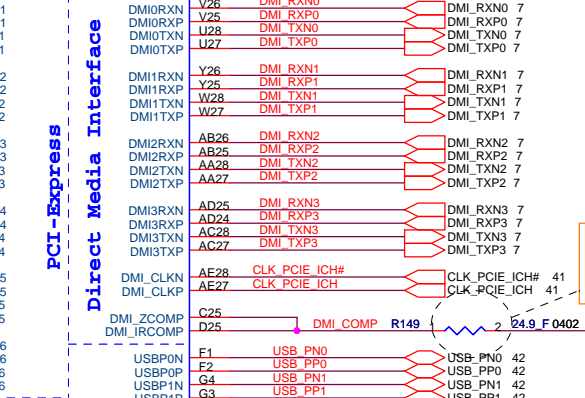
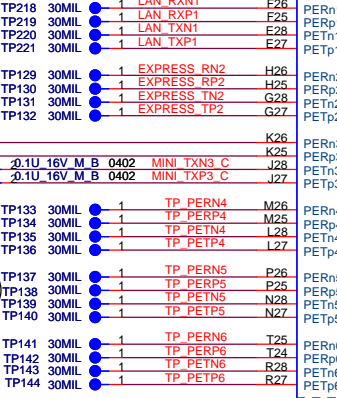
Internal PH 20K



Strap for Boot-BIOS		
	GNT5#	GNT4#
LPC	H	H
PCI	H	L
SPI(default)	L	H

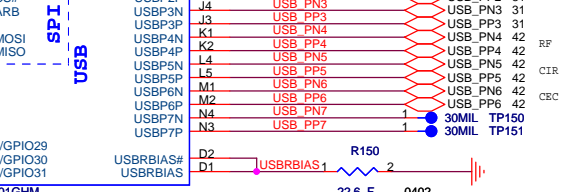
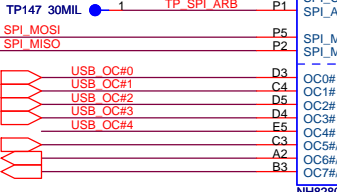
Test leakage voltage in BB

U12D



Place within 500 mils of ICH

SPI



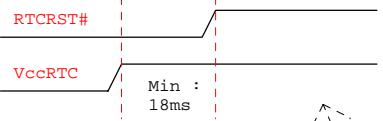
Place within 500 mils of ICH and don't routing next to high speed signals

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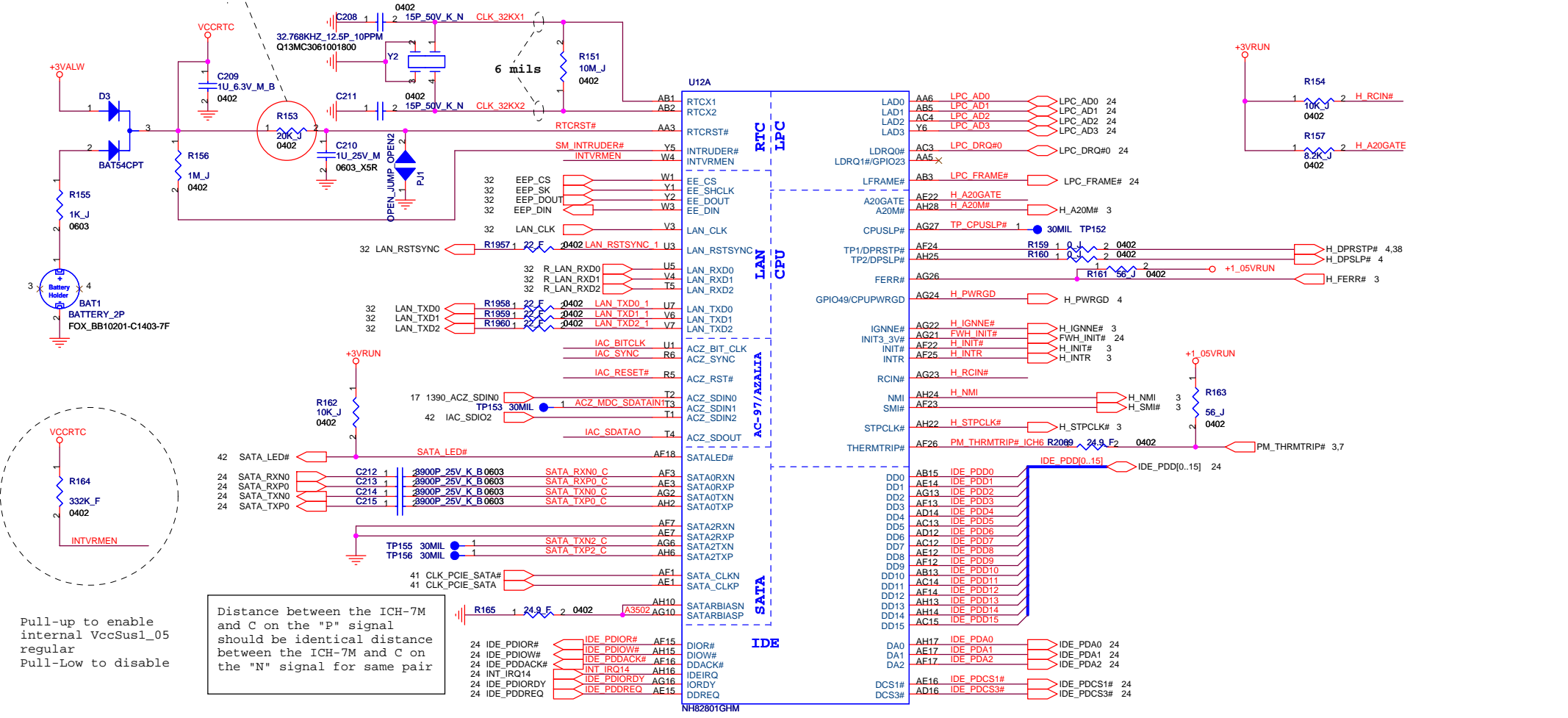
Title: **ICH7-M(PCI/DMI/USB/PCIE) 1/5**

Size A3 Document Number **MS80-1-04** Rev 0.1

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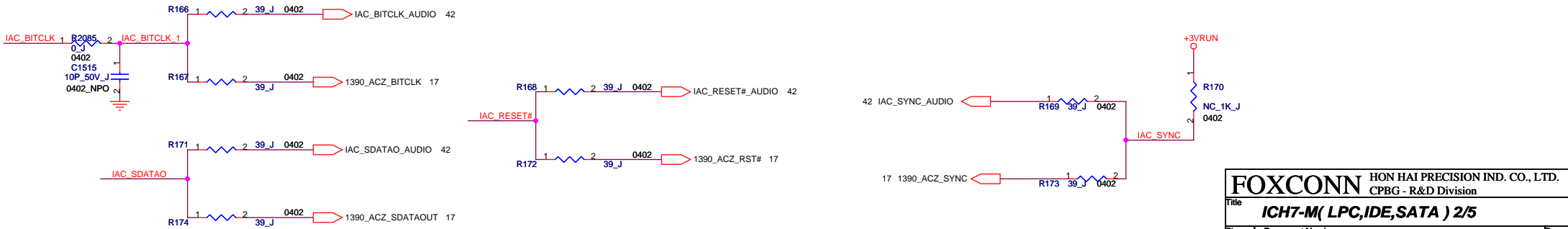


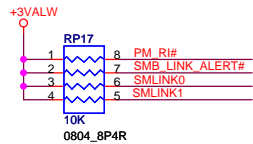
The traces inside this block should be wider.
No digital signals routed under XTAL



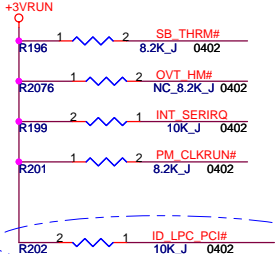
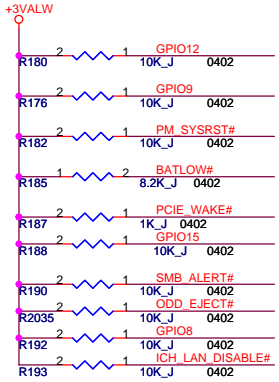
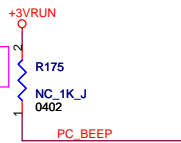
Pull-up to enable internal VccSus1_05 regular
Pull-Low to disable

Distance between the ICH-7M and C on the "P" signal should be identical distance between the ICH-7M and C on the "N" signal for same pair

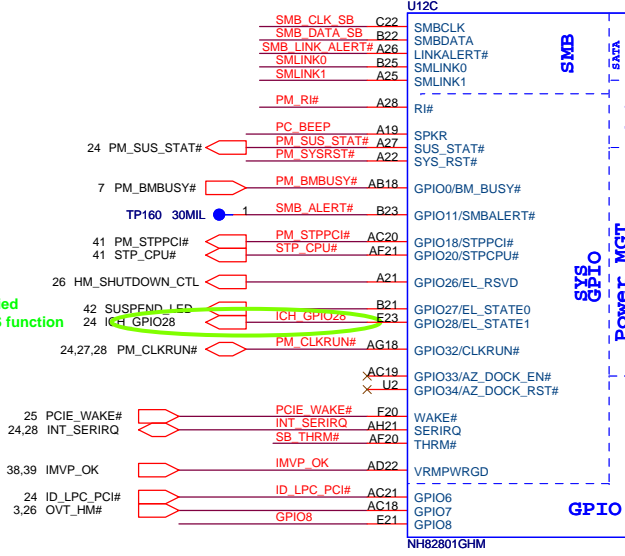




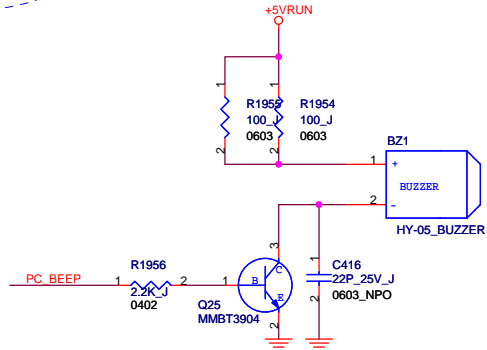
Stuff for No-reboot



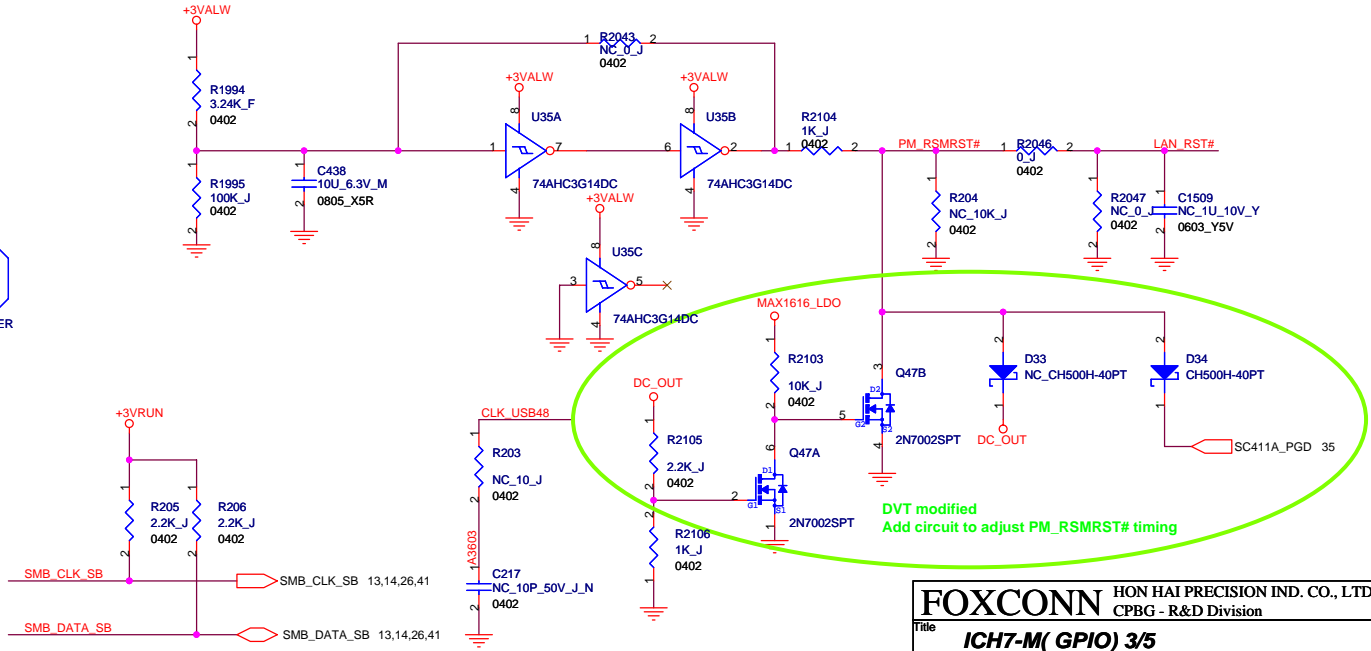
80 Port I/F:
H: LPC bus
L: PCI bus



DVT modified
Add X-BUS function

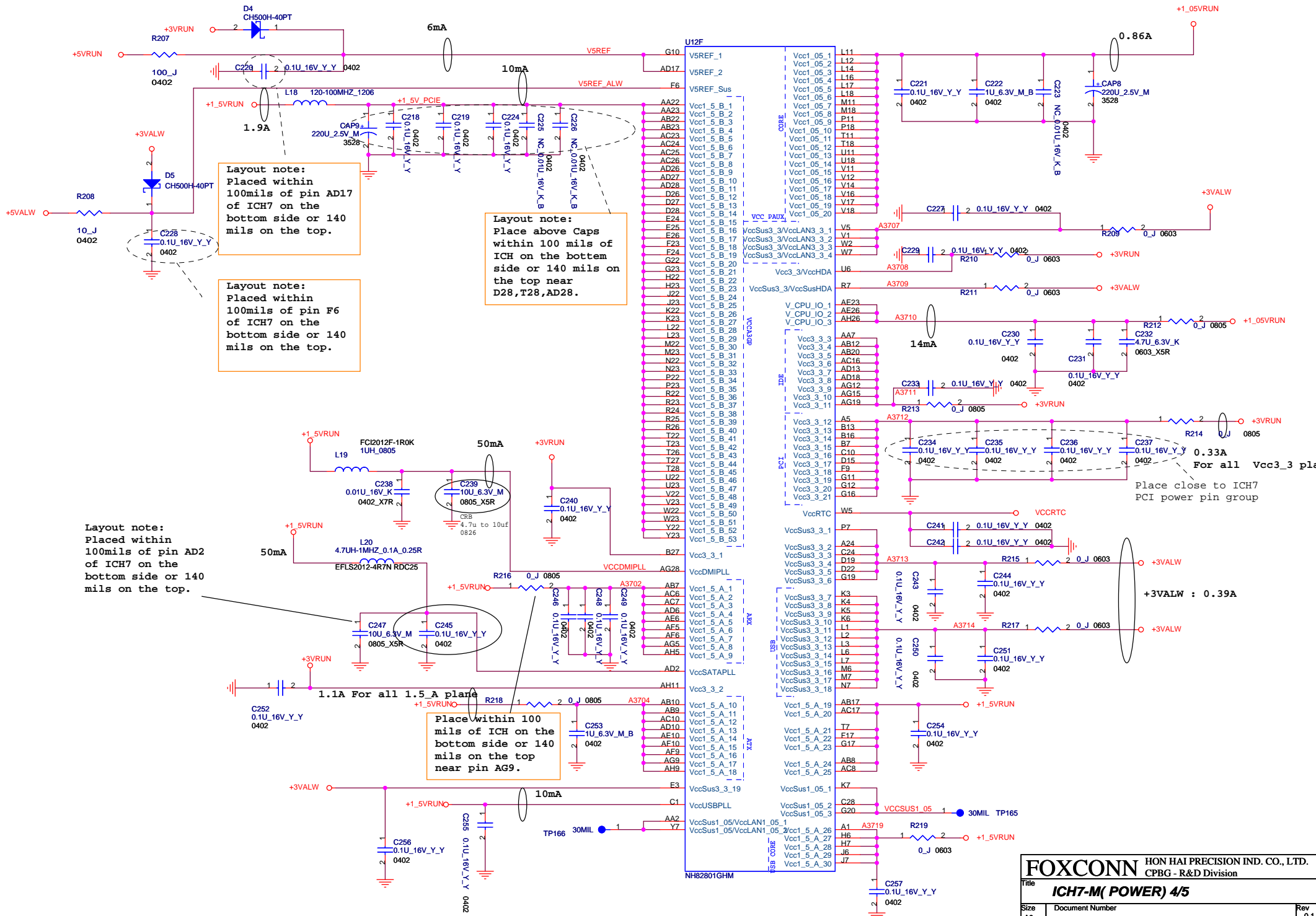


BUZZER



DVT modified
Add circuit to adjust PM_RSMRST# timing

FOXCONN HON HAI PRECISION IND. CO., LTD. CPBG - R&D Division		
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Layout note:
Placed within 100mils of pin AD17 of ICH7 on the bottom side or 140 mils on the top.

Layout note:
Placed within 100mils of pin F6 of ICH7 on the bottom side or 140 mils on the top.

Layout note:
Place above Caps within 100 mils of ICH on the bottom side or 140 mils on the top near D28, T28, AD28.

Layout note:
Placed within 100mils of pin AD2 of ICH7 on the bottom side or 140 mils on the top.

Layout note:
Place within 100 mils of ICH on the bottom side or 140 mils on the top near pin AG9.

For all Vcc3_3 plane
Place close to ICH7 PCI power pin group

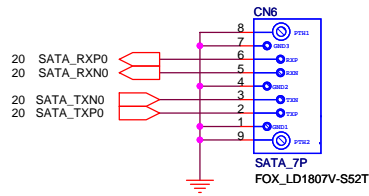
FOXCONN HON HAI PRECISION IND. CO., LTD. CPBG - R&D Division		
Title ICH7-M(POWER) 4/5		
Size A3	Document Number MS80-1-04	Rev 0.1
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U12E			P28
A4	VSS_1	VSS_98	R1
A23	VSS_2	VSS_99	R11
B1	VSS_3	VSS_100	R12
B8	VSS_4	VSS_101	R13
B11	VSS_5	VSS_102	R14
B14	VSS_6	VSS_103	R15
B17	VSS_7	VSS_104	R16
B20	VSS_8	VSS_105	R17
B26	VSS_9	VSS_106	R18
B28	VSS_10	VSS_107	T6
C2	VSS_11	VSS_108	T12
C6	VSS_12	VSS_109	T13
C27	VSS_13	VSS_110	T14
D10	VSS_14	VSS_111	T15
D13	VSS_15	VSS_112	T16
D18	VSS_16	VSS_113	T17
D21	VSS_17	VSS_114	U4
D24	VSS_18	VSS_115	U12
E1	VSS_19	VSS_116	U13
E2	VSS_20	VSS_117	U14
F4	VSS_21	VSS_118	U15
F8	VSS_22	VSS_119	U16
F15	VSS_23	VSS_120	U17
F3	VSS_24	VSS_121	U24
F4	VSS_25	VSS_122	U25
F5	VSS_26	VSS_123	U26
F12	VSS_27	VSS_124	V2
F27	VSS_28	VSS_125	V13
F28	VSS_29	VSS_126	V15
G1	VSS_30	VSS_127	V24
G2	VSS_31	VSS_128	V27
G5	VSS_32	VSS_129	V28
G6	VSS_33	VSS_130	W6
G9	VSS_34	VSS_131	W24
G14	VSS_35	VSS_132	W25
G18	VSS_36	VSS_133	W26
G21	VSS_37	VSS_134	Y3
G24	VSS_38	VSS_135	Y24
G25	VSS_39	VSS_136	Y27
G26	VSS_40	VSS_137	Y28
H3	VSS_41	VSS_138	AA1
H4	VSS_42	VSS_139	AA24
H5	VSS_43	VSS_140	AA25
H24	VSS_44	VSS_141	AA26
H27	VSS_45	VSS_142	AB4
H28	VSS_46	VSS_143	AB6
J1	VSS_47	VSS_144	AB11
J2	VSS_48	VSS_145	AB14
J5	VSS_49	VSS_146	AB16
J24	VSS_50	VSS_147	AB19
J25	VSS_51	VSS_148	AB21
J26	VSS_52	VSS_149	AB24
K24	VSS_53	VSS_150	AB27
K27	VSS_54	VSS_151	AB28
K28	VSS_55	VSS_152	AC2
L13	VSS_56	VSS_153	AC5
L15	VSS_57	VSS_154	AC9
L24	VSS_58	VSS_155	AC11
L25	VSS_59	VSS_156	AD1
L26	VSS_60	VSS_157	AD3
M3	VSS_61	VSS_158	AD4
M4	VSS_62	VSS_159	AD7
M5	VSS_63	VSS_160	AD8
M12	VSS_64	VSS_161	AD11
M13	VSS_65	VSS_162	AD15
M14	VSS_66	VSS_163	AD19
M15	VSS_67	VSS_164	AD23
M16	VSS_68	VSS_165	AE2
M17	VSS_69	VSS_166	AE4
M24	VSS_70	VSS_167	AE8
M27	VSS_71	VSS_168	AE11
M28	VSS_72	VSS_169	AE13
N1	VSS_73	VSS_170	AE18
N2	VSS_74	VSS_171	AE21
N5	VSS_75	VSS_172	AE24
N6	VSS_76	VSS_173	AE25
N11	VSS_77	VSS_174	AF2
N12	VSS_78	VSS_175	AF4
N13	VSS_79	VSS_176	AF8
N14	VSS_80	VSS_177	AF11
N15	VSS_81	VSS_178	AF27
N16	VSS_82	VSS_179	AF28
N17	VSS_83	VSS_180	AG1
N18	VSS_84	VSS_181	AG3
N24	VSS_85	VSS_182	AG7
N25	VSS_86	VSS_183	AG11
N26	VSS_87	VSS_184	AG14
P3	VSS_88	VSS_185	AG17
P4	VSS_89	VSS_186	AG20
P12	VSS_90	VSS_187	AG25
P13	VSS_91	VSS_188	AH1
P14	VSS_92	VSS_189	AH3
P15	VSS_93	VSS_190	AH7
P16	VSS_94	VSS_191	AH12
P17	VSS_95	VSS_192	AH23
P24	VSS_96	VSS_193	AH27
P27	VSS_97	VSS_194	

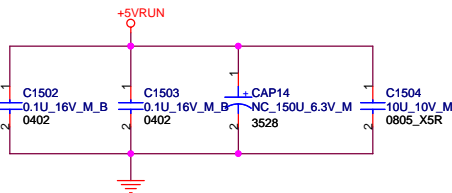
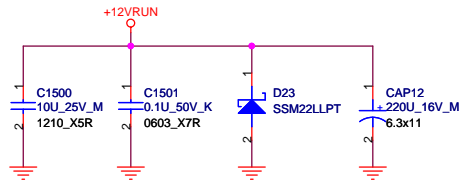
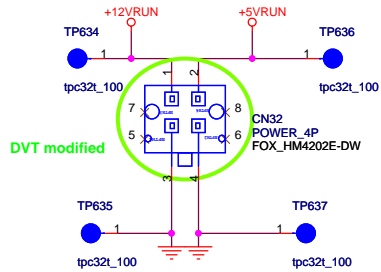
NH82801GHM

FOXCONN		HON HAI PRECISION IND. CO., LTD.	
		CPBG - R&D Division	
Title			
ICH7-M(GND) 5/5			
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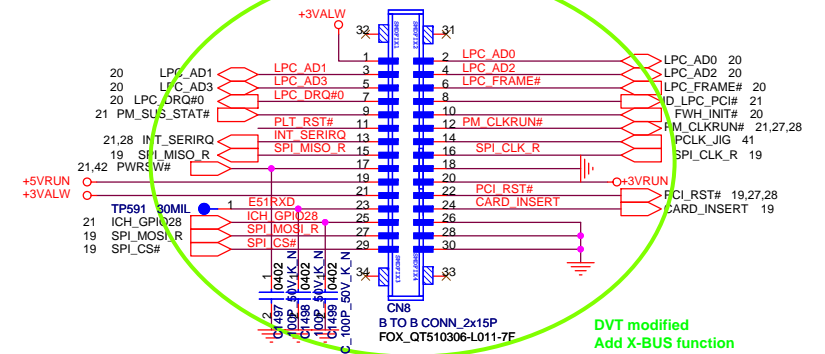
SATA HDD CONN



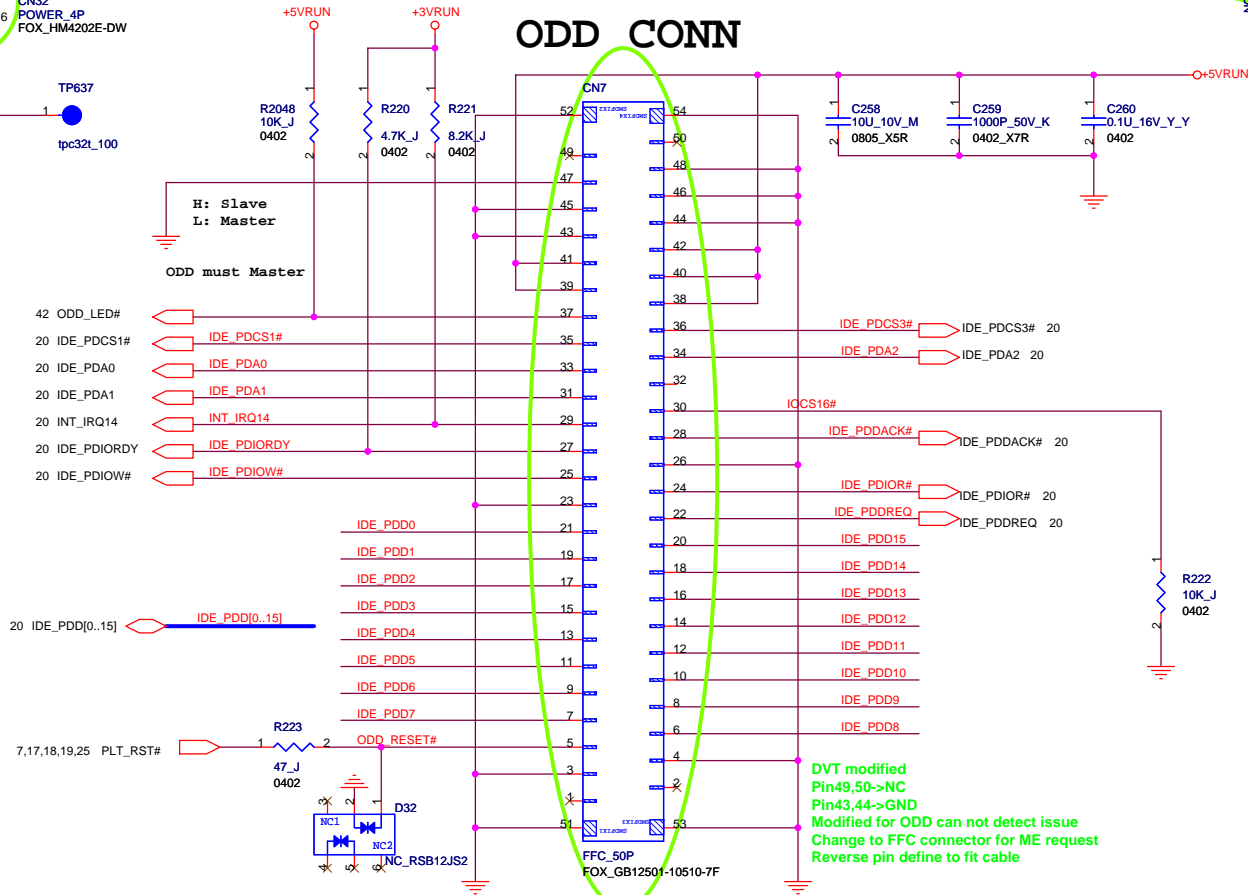
SATA HDD PWR

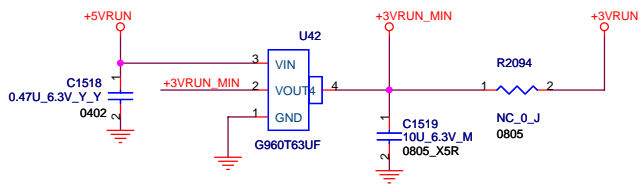
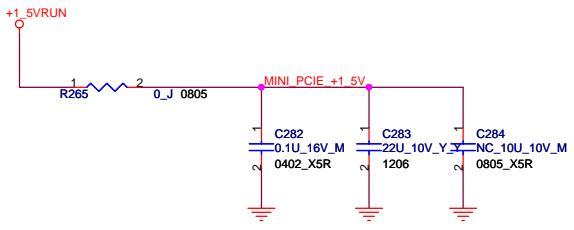
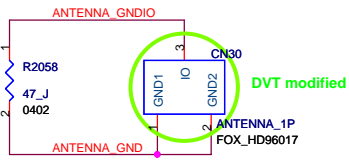
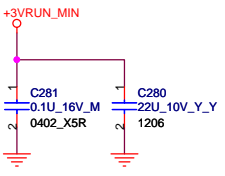
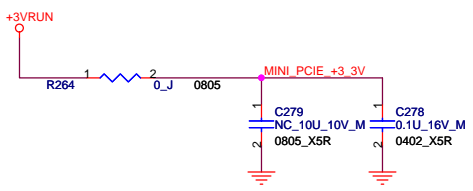
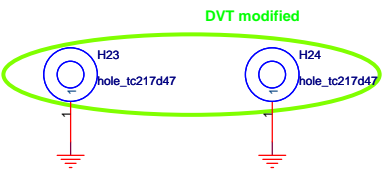
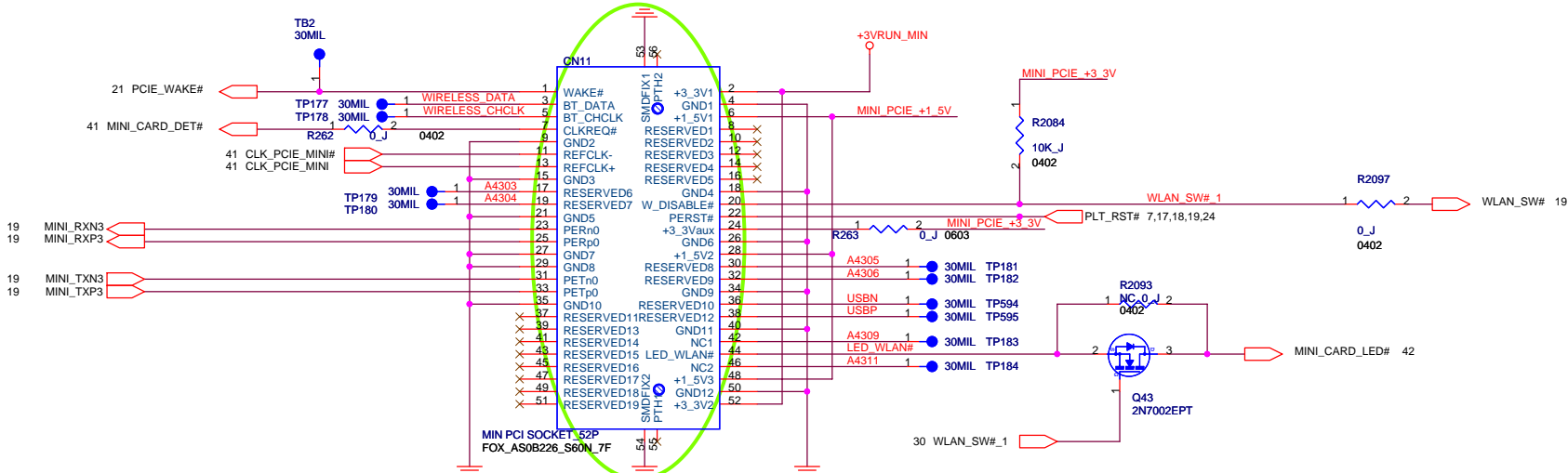


JIG-120

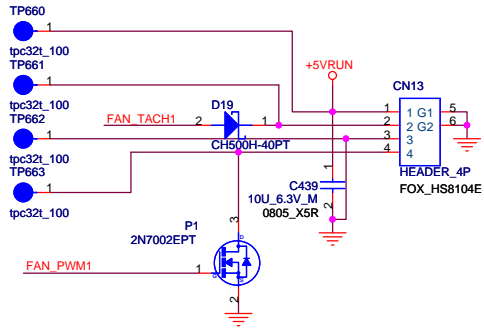


ODD CONN



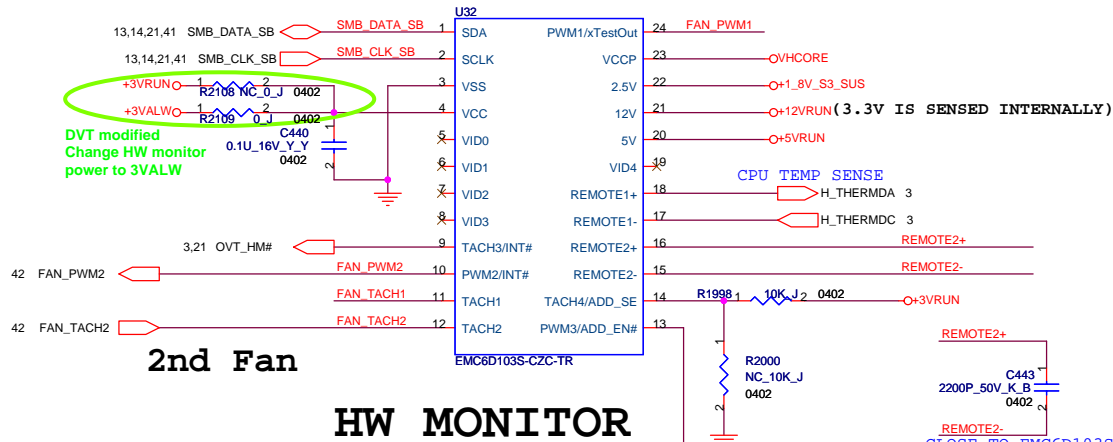
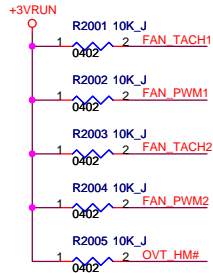


FOXCONN HON HAI PRECISION IND. CO., LTD.		
CPBG - R&D Division		
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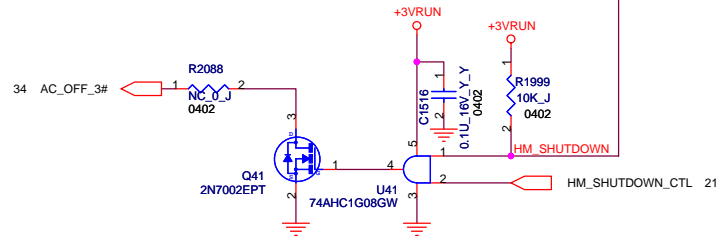
CPU FAN CONN

CHECK PIN DEFINITION WITH THERMAL TEAM

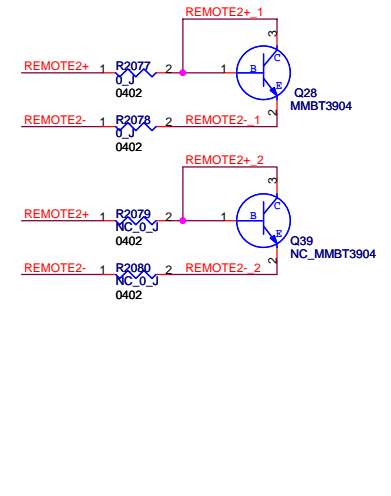


2nd Fan

HW MONITOR

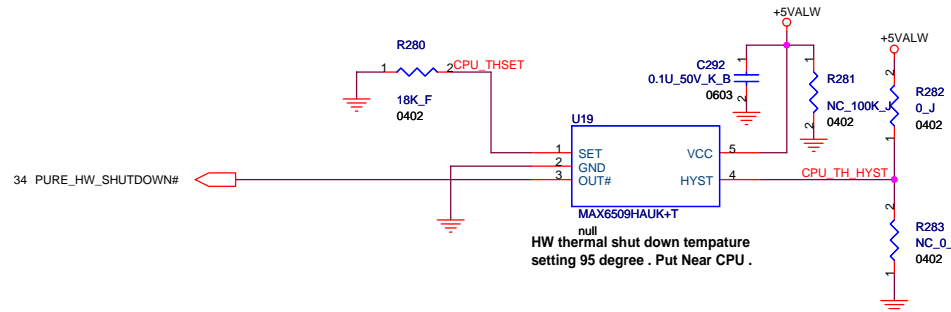


SYSTEM TEMP SENSE

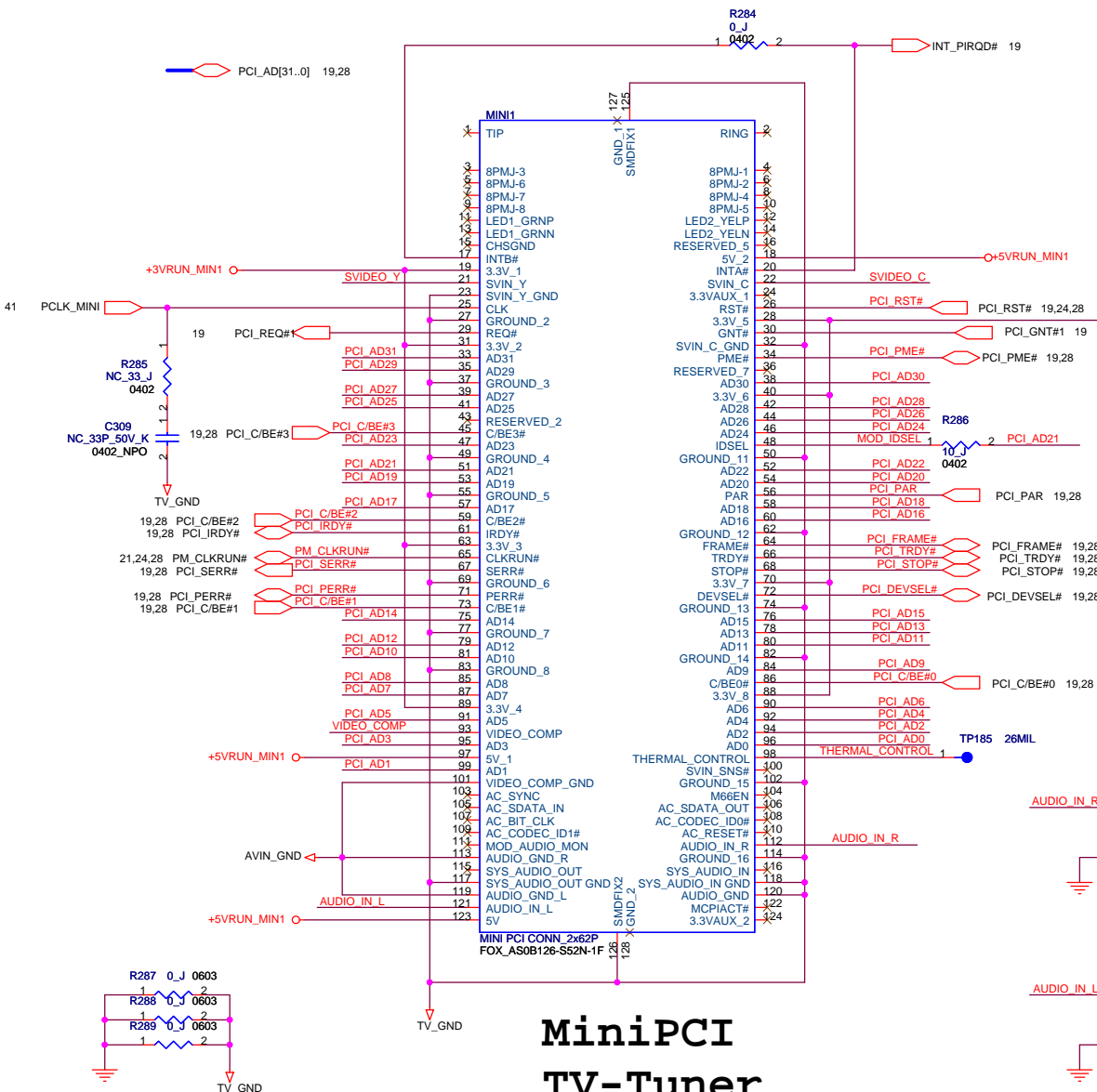
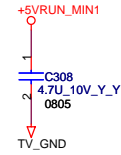
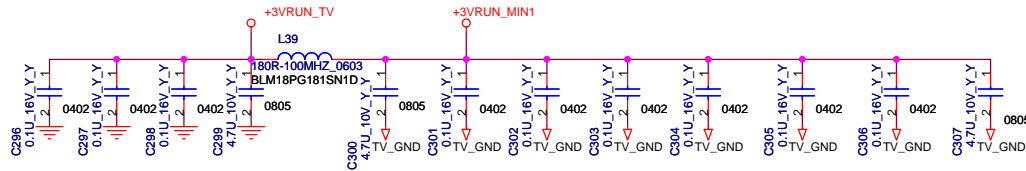
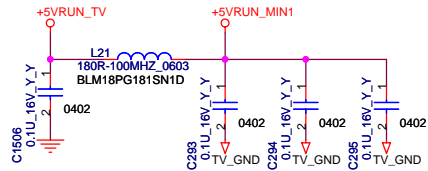


For 0 degree to +125 degree
 $R_{set}(kohm) = [(8.3793 \times 10000) / T] - 211.3569 + [(1.2989 \times 100000) / T \times T]$
 T=kelvin temperature

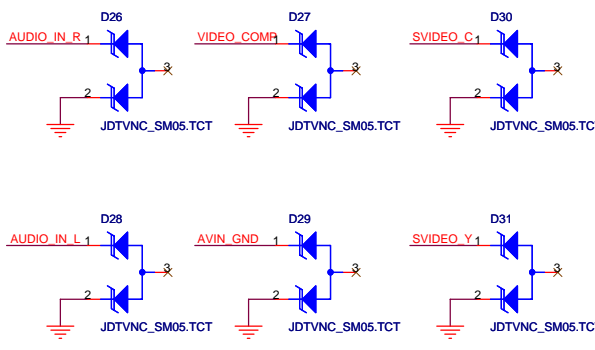
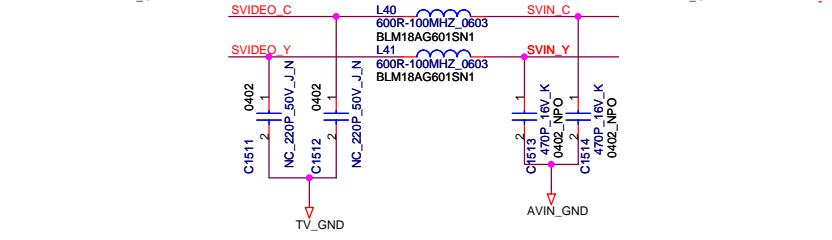
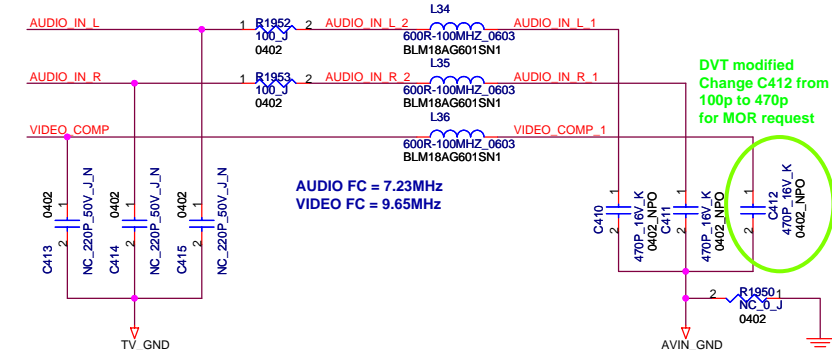
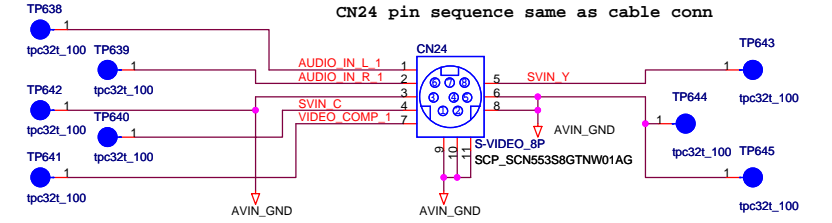
HW THERMAL PROTECTION



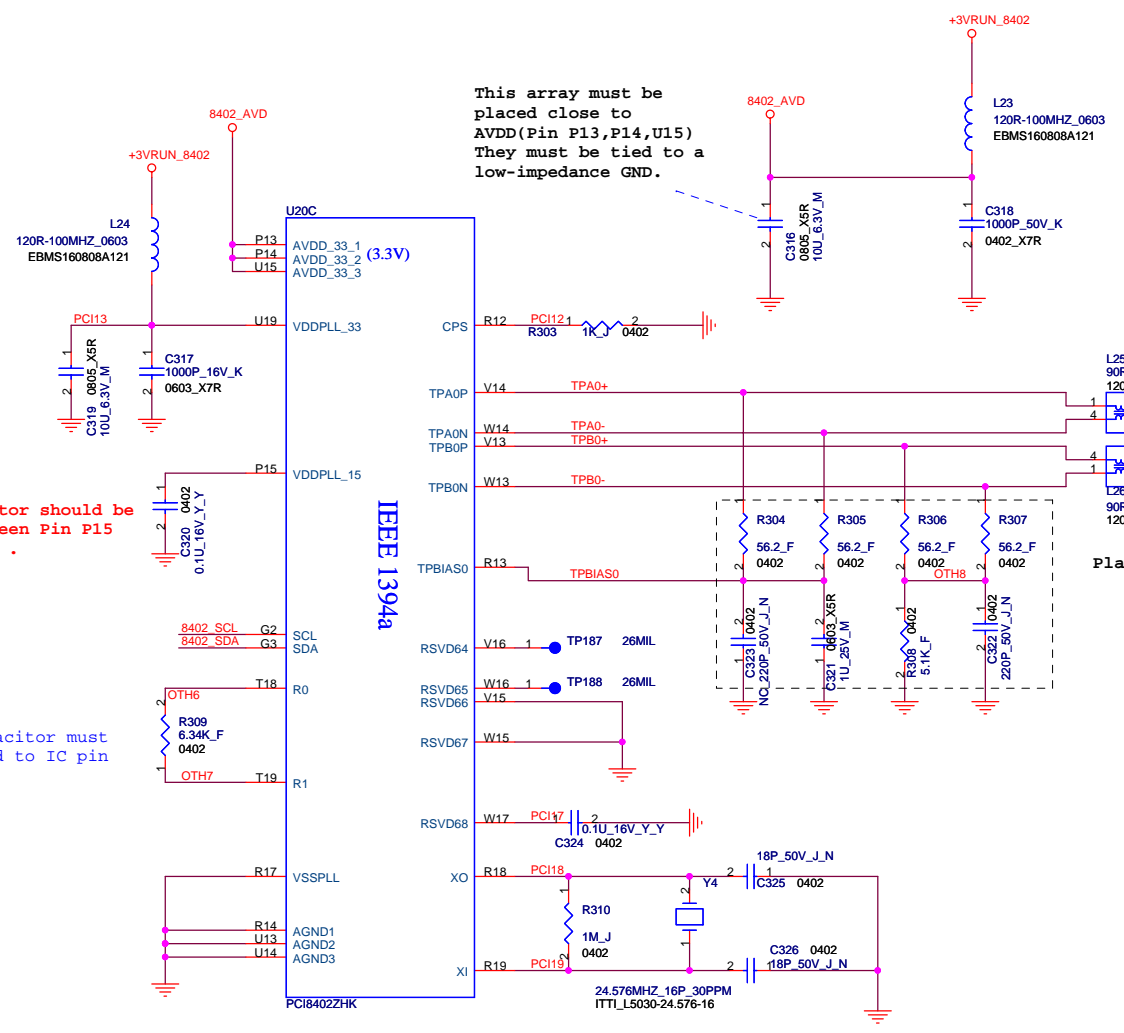
FOXCONN HON HAI PRECISION IND. CO., LTD.		
CPBG - R&D Division		
Title HWMONITOR/FAN/HWPROTECT		
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MiniPCI TV-Tuner



FOXCONN HON HAI PRECISION IND. CO., LTD.	
CPBG - R&D Division	
Title MINIPCI_TV_TUNER	
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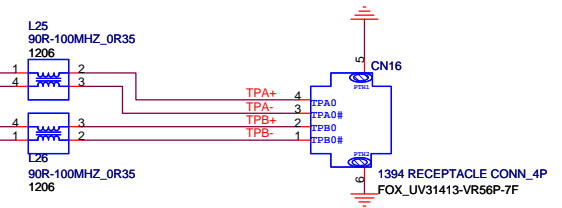
This array must be placed close to AVDD (Pin P13,P14,U15) They must be tied to a low-impedance GND.

This capacitor should be placed between Pin P15 and Pin R17 .

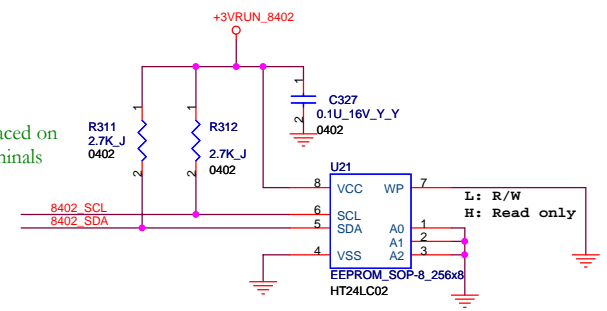
This capacitor must be placed to IC pin

Place near PCI8402

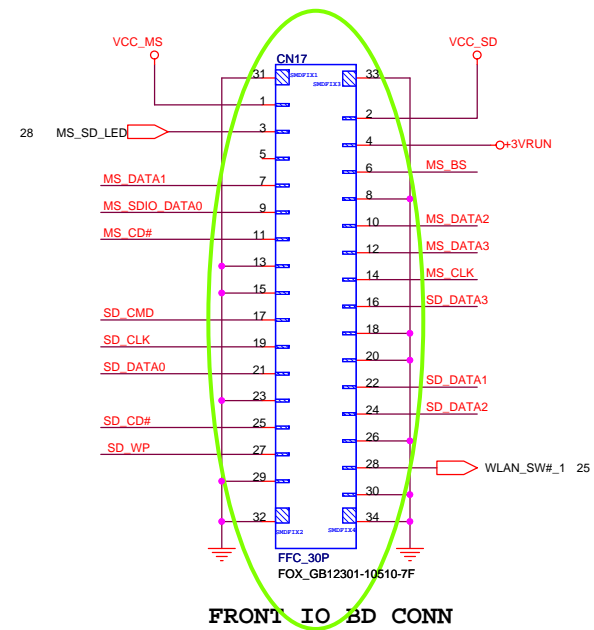
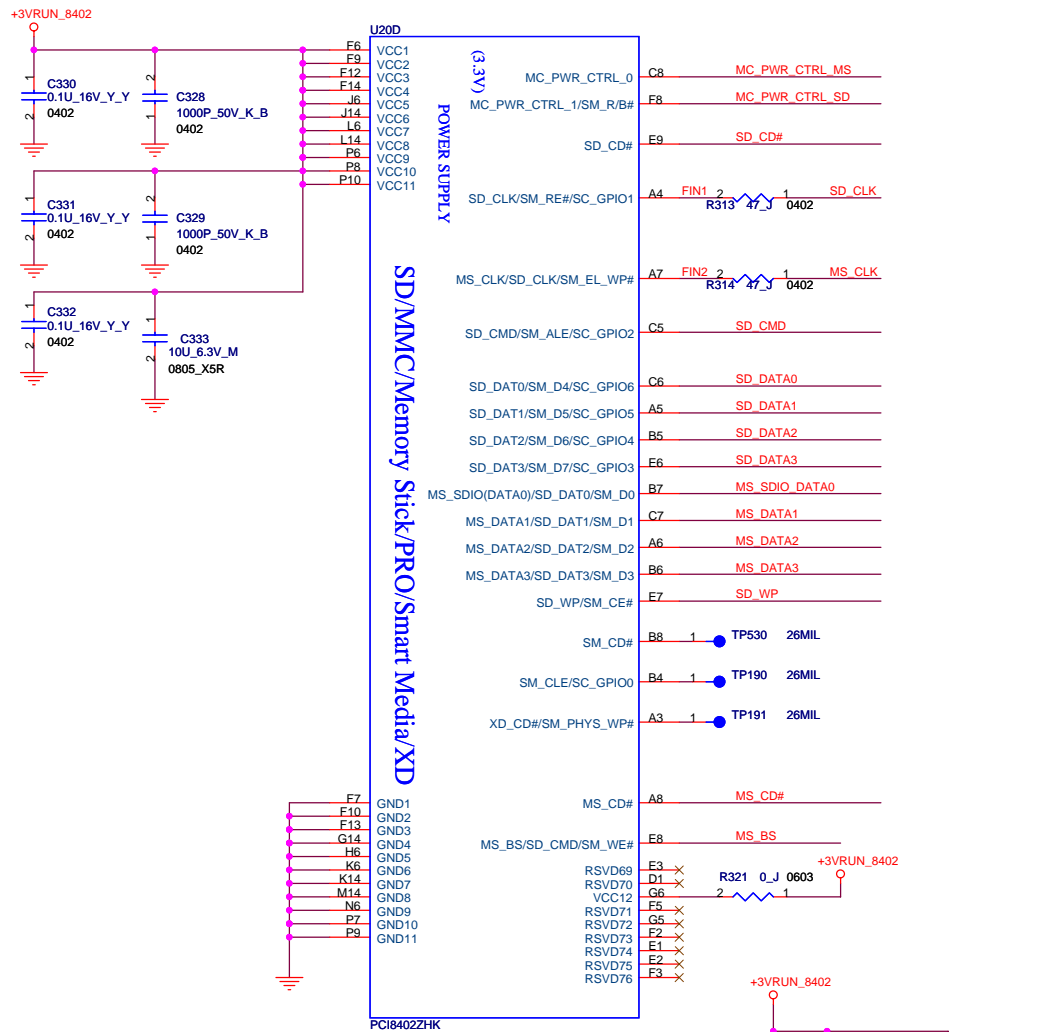
iLink CONN.



Resistors should be placed on the SCL and SDA terminals

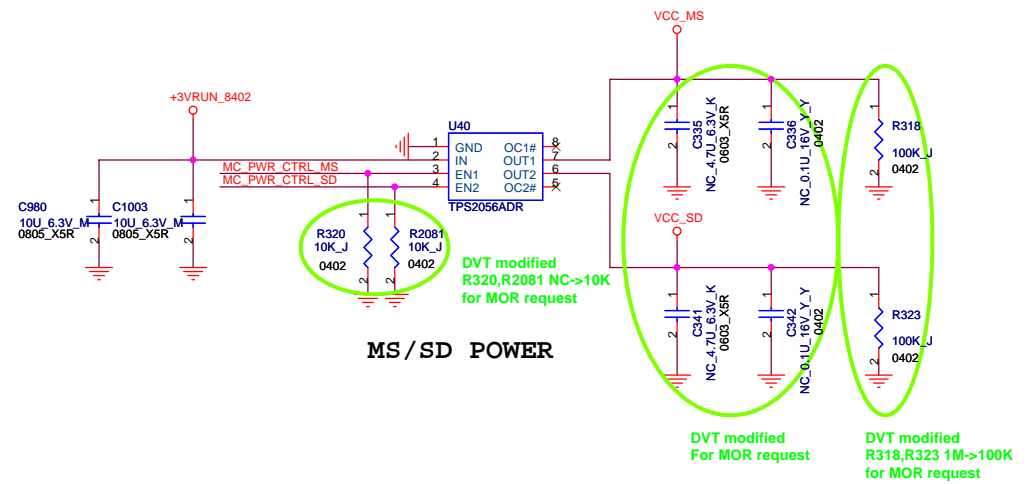


FOXCONN HON HAI PRECISION IND. CO., LTD.	
CPBG - R&D Division	
Title PCI (I LINK)	
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FRONT IO BD CONN

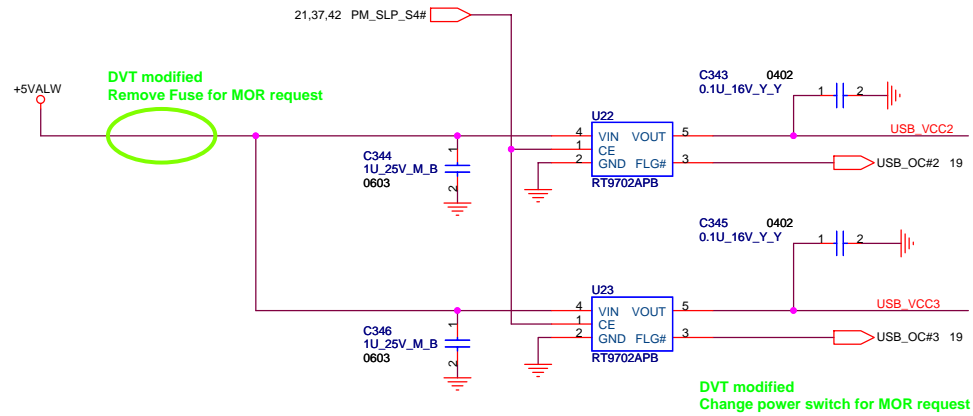
DVT modified
For ME request



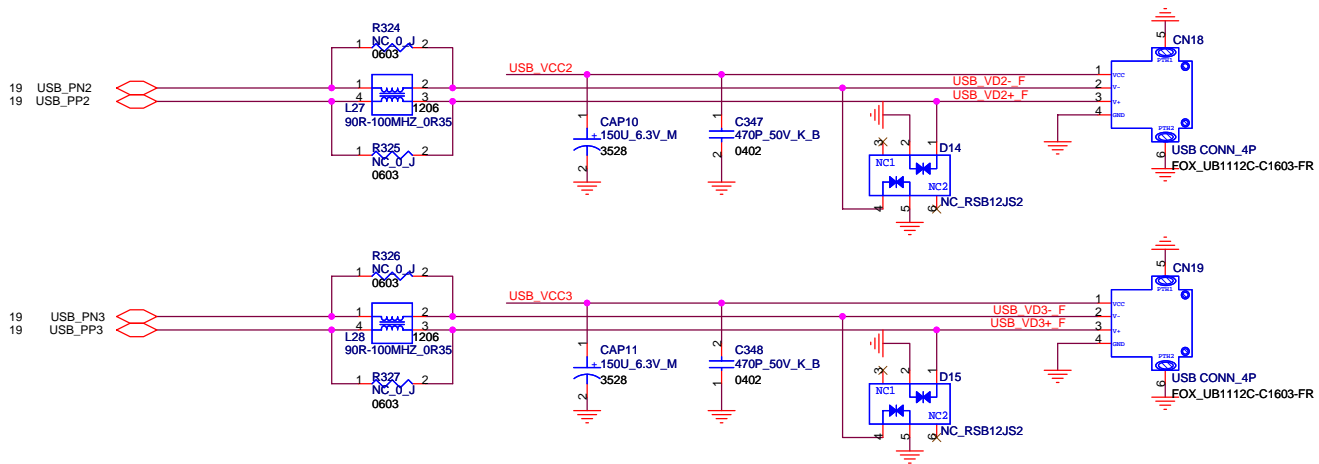
DVT modified
R320,R2081 NC->10K
for MOR request

DVT modified
For MOR request

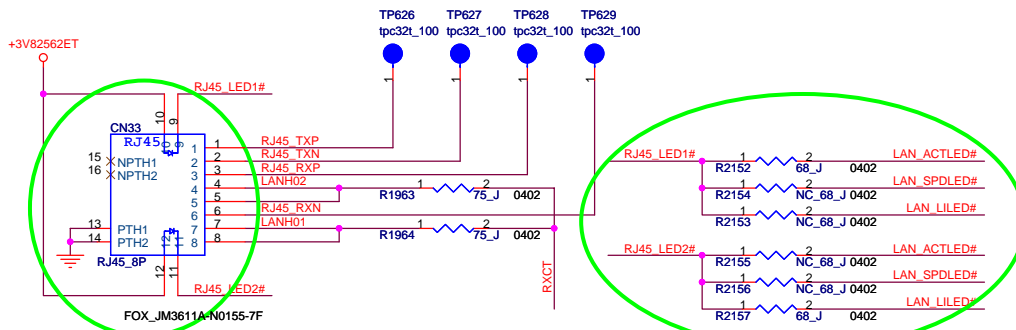
DVT modified
R318,R323 1M->100K
for MOR request



USB Power Switch

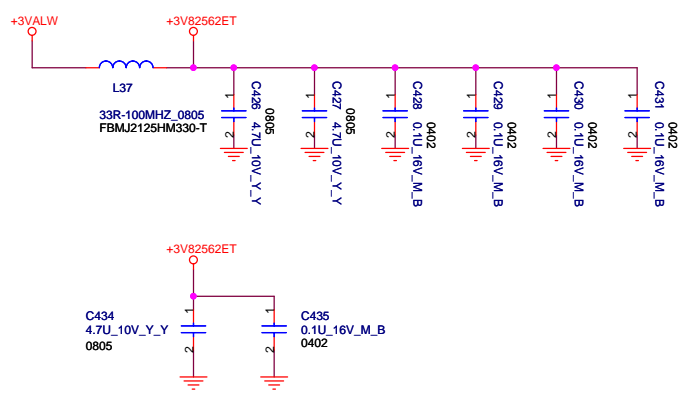
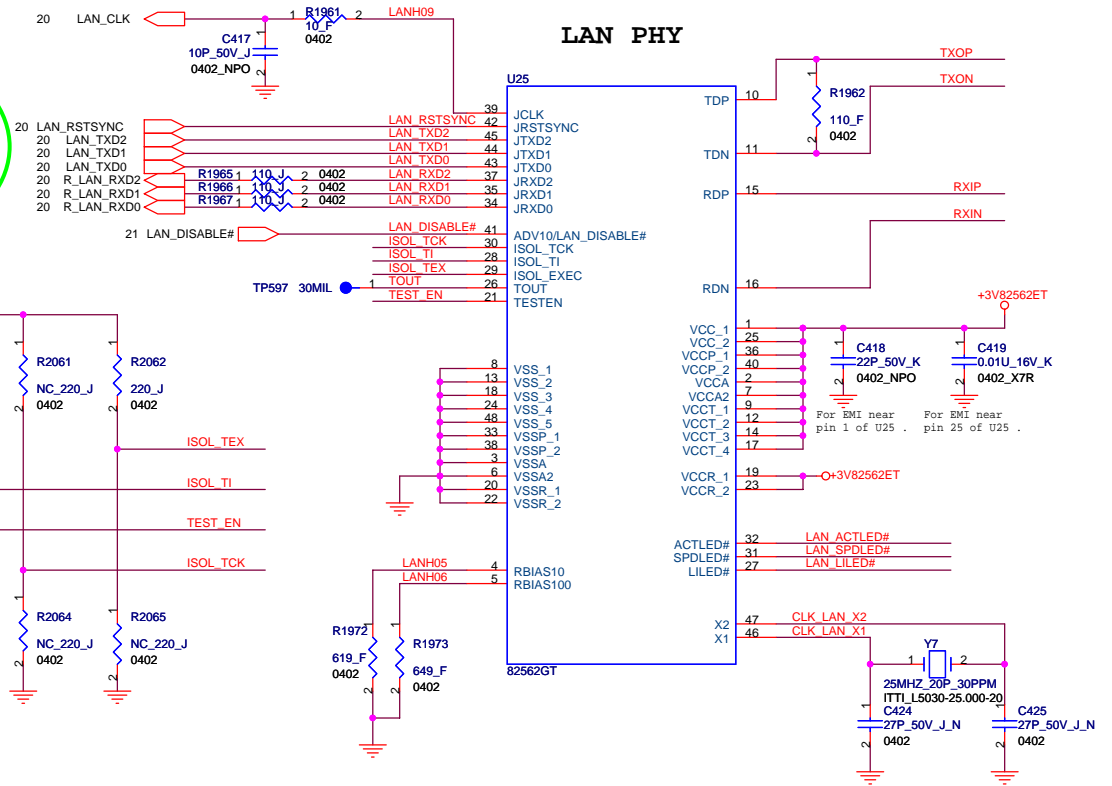
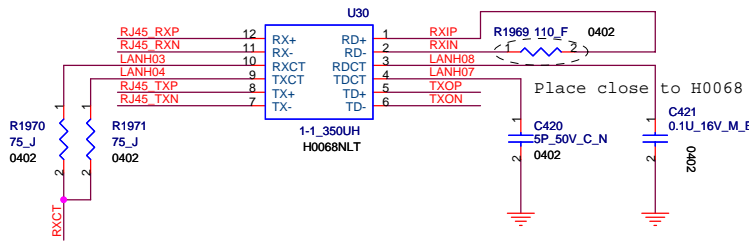


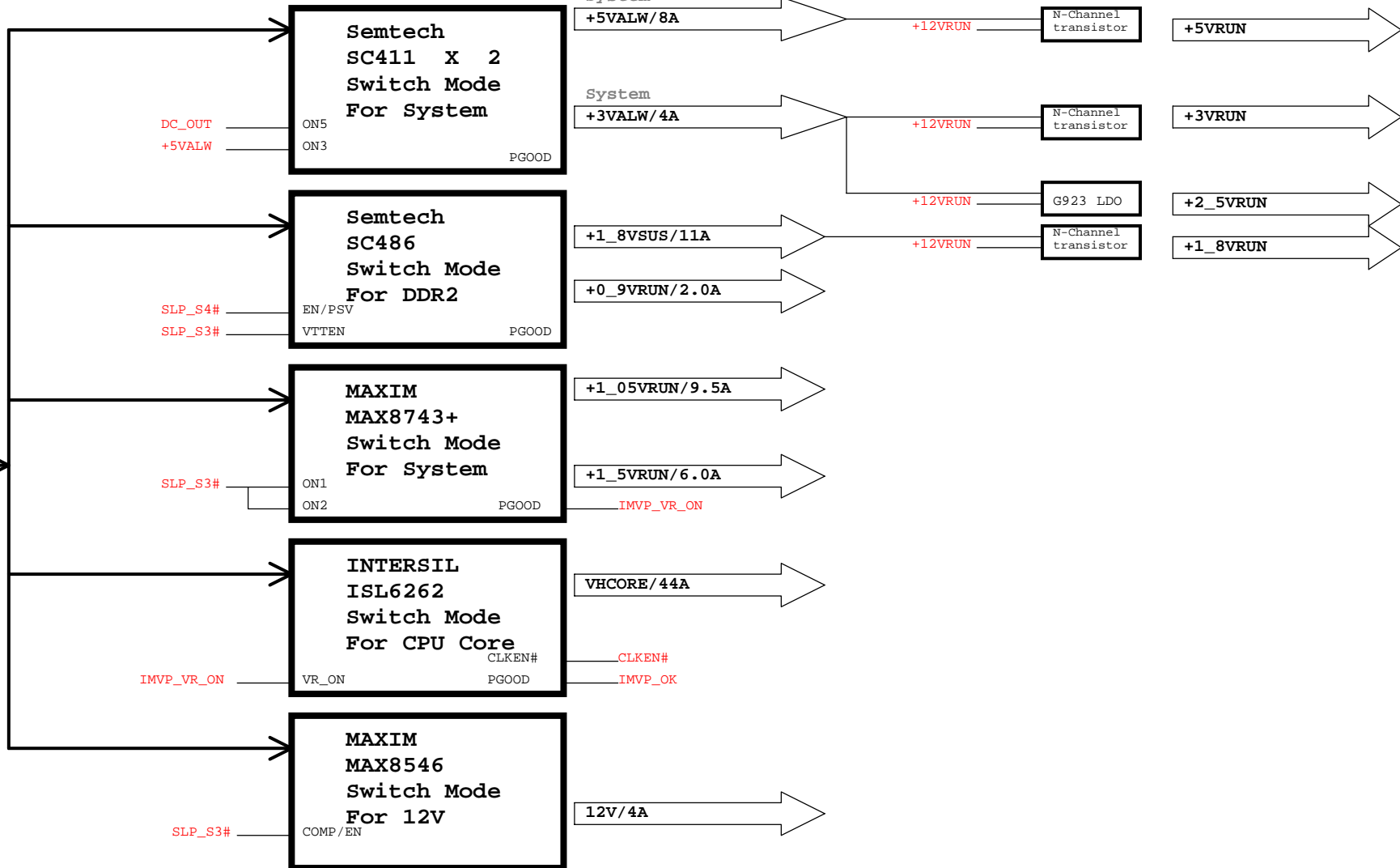
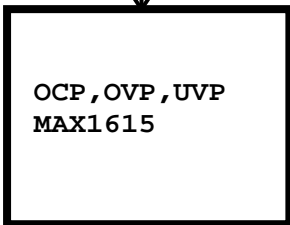
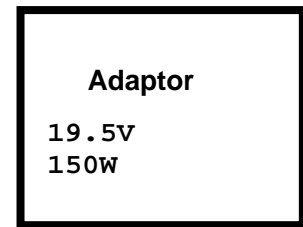
USB

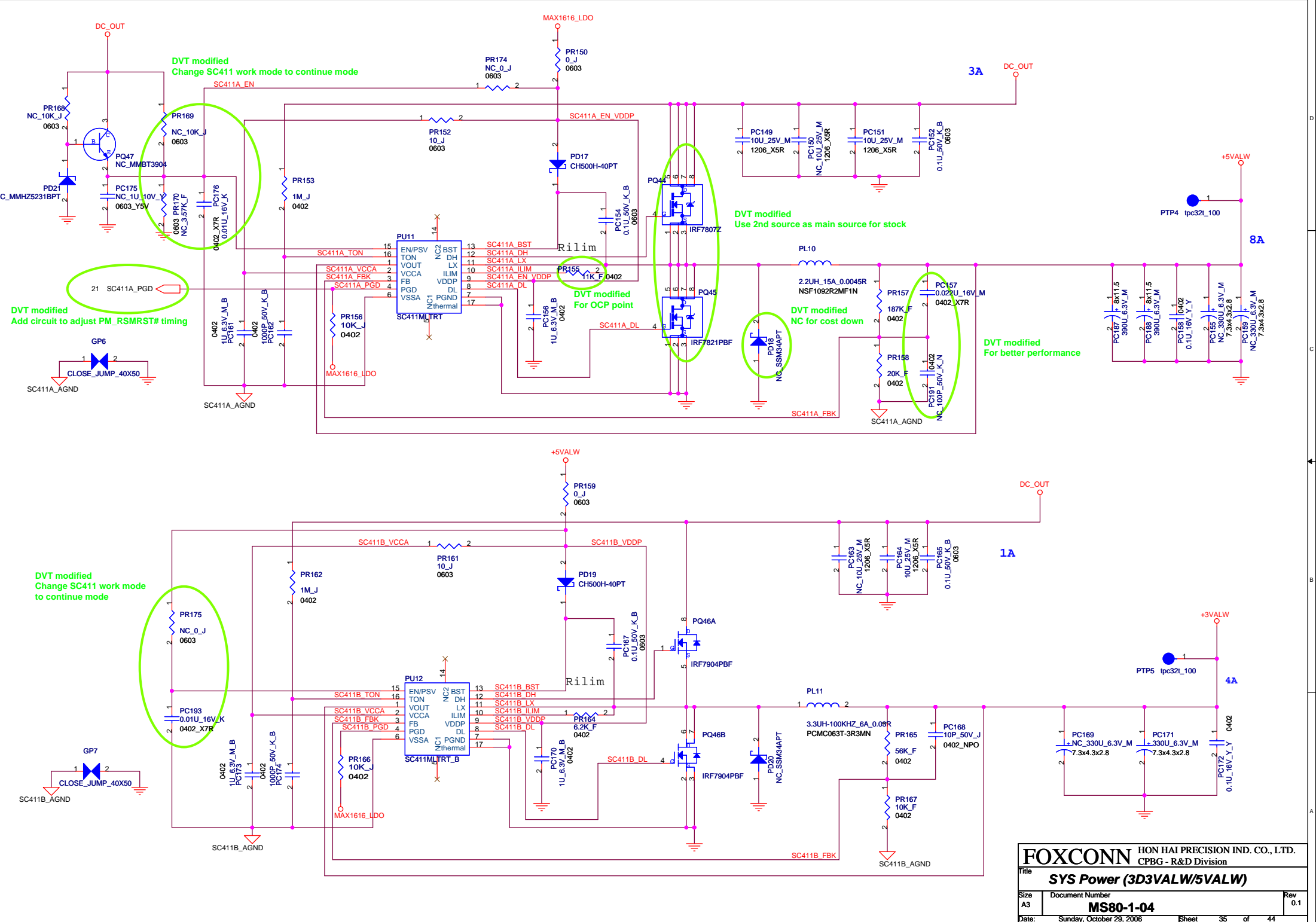


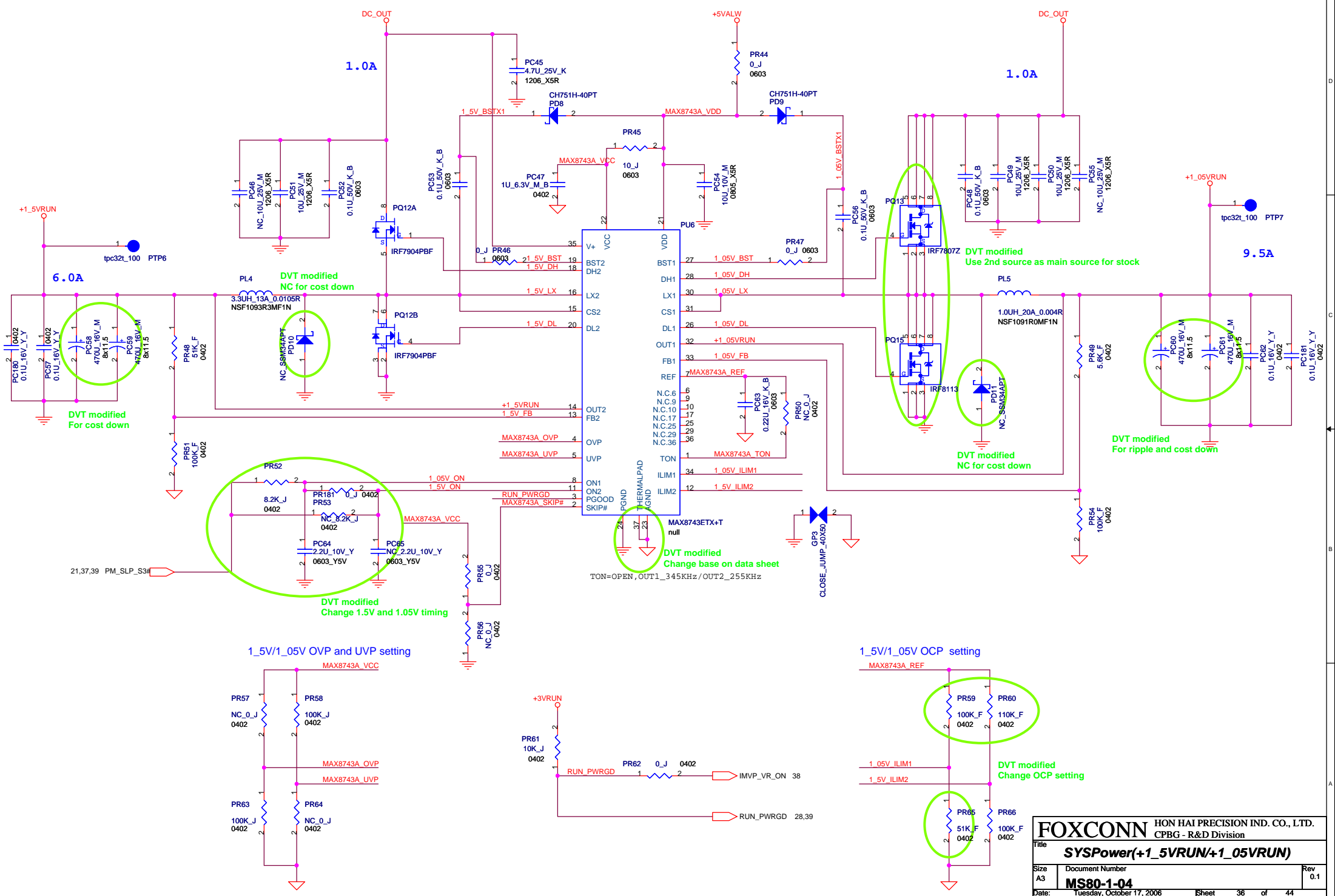
DVT modified
change color

DVT modified
Add LED

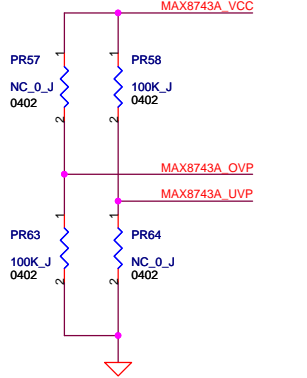




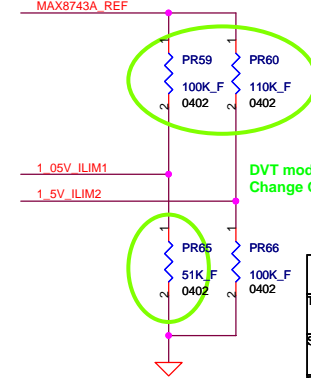


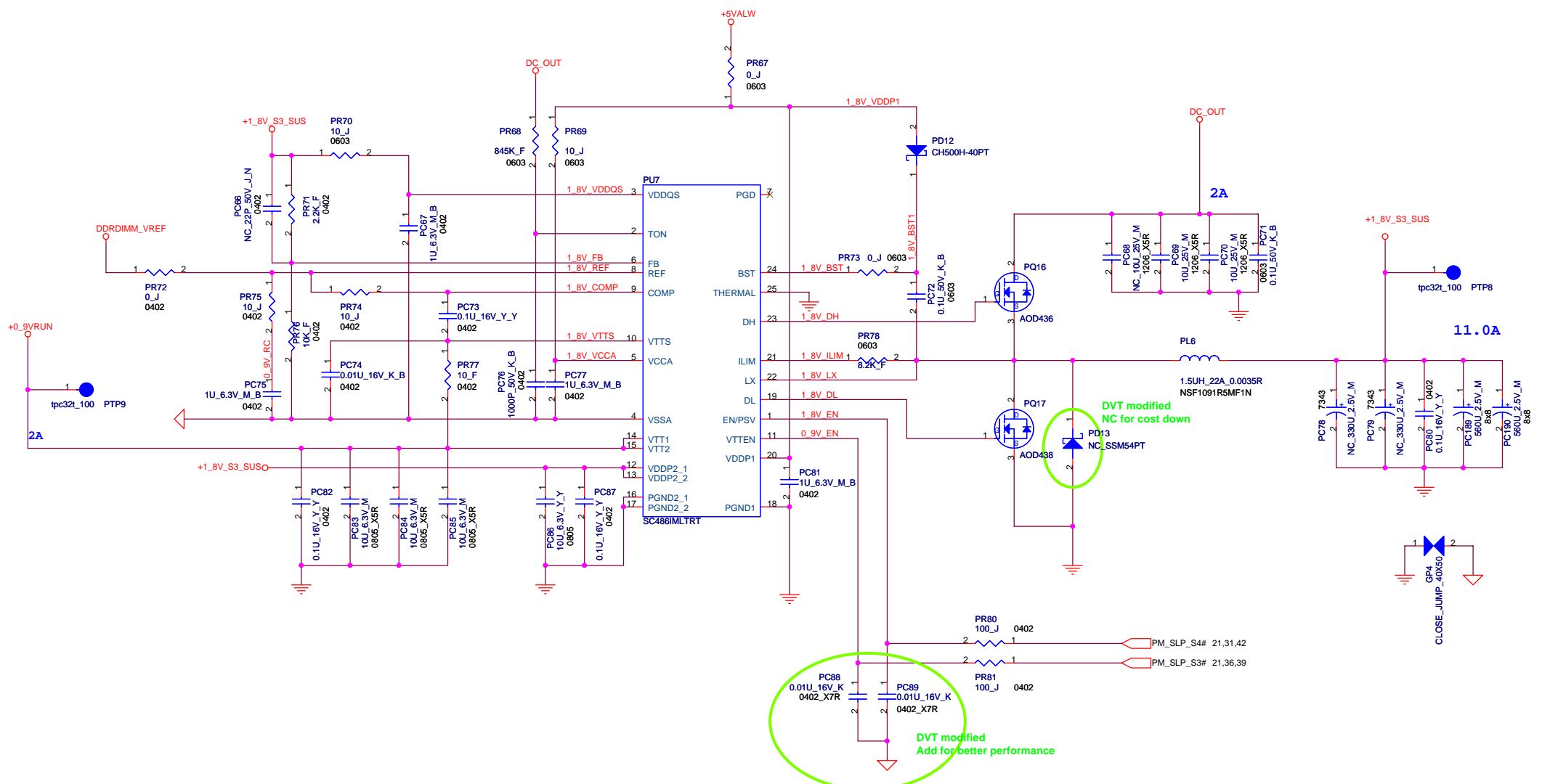


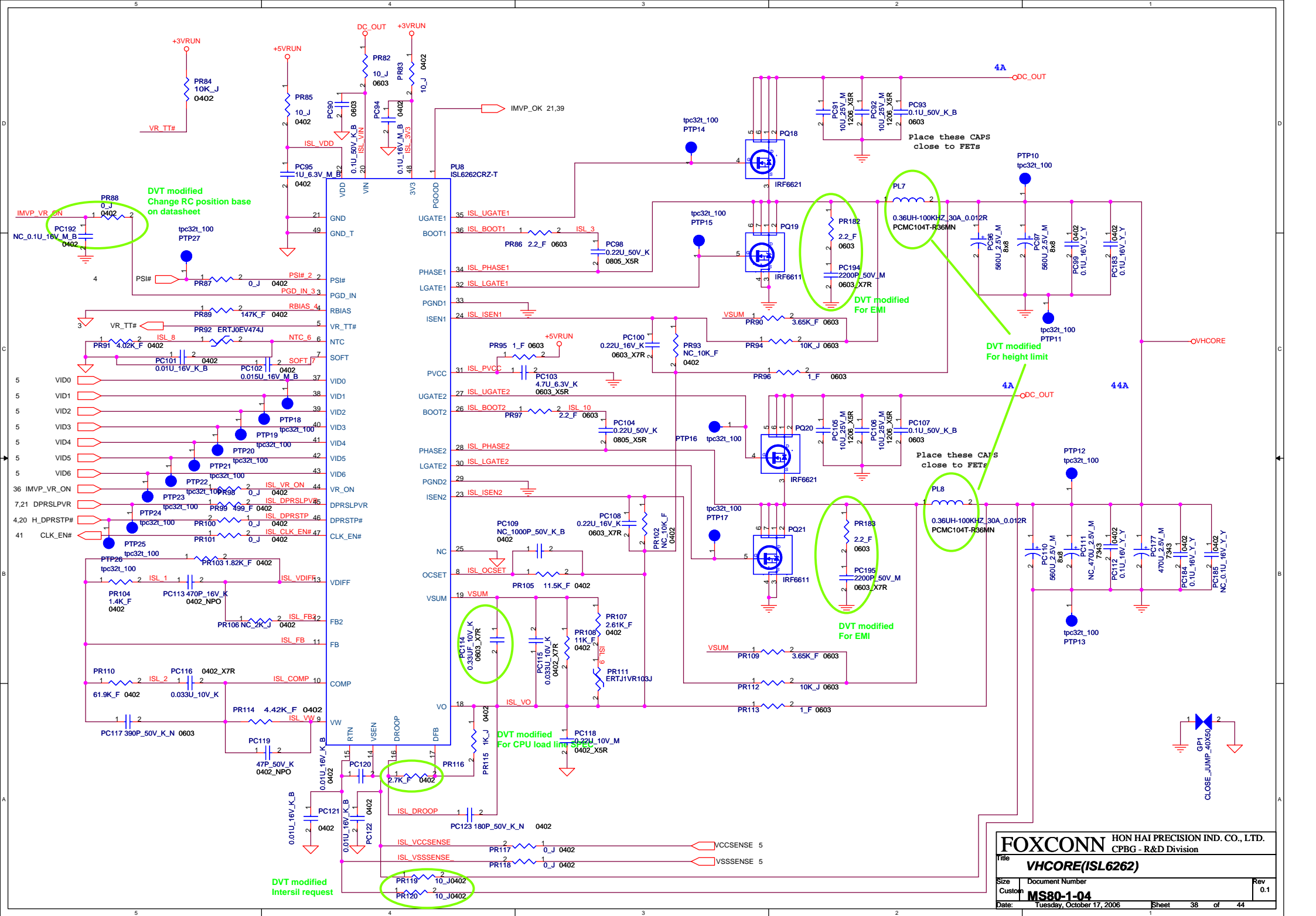
1.5V/1.05V OVP and UVP setting



1.5V/1.05V OCP setting







IMVP_VR_ON
 NC_0.1U_16V_M_B
 0402

DVT modified
 Change RC position base
 on datasheet

Place these CAPS
 close to FETs

DVT modified
 For EMI

DVT modified
 For height limit

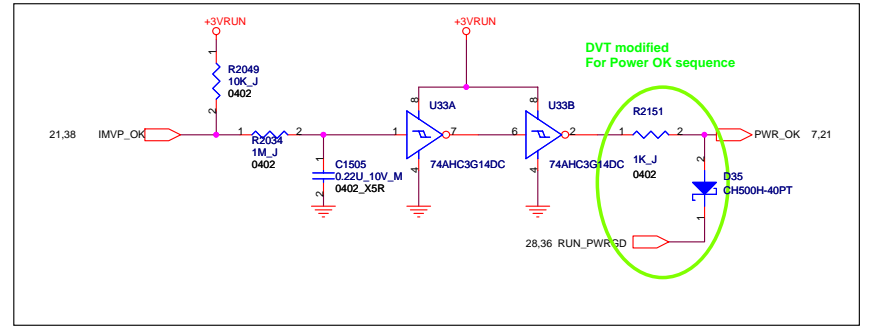
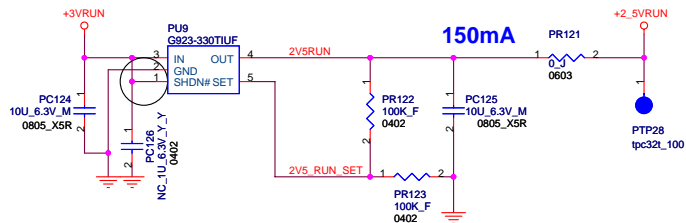
DVT modified
 For EMI

DVT modified
 For CPU load line

Place these CAPS
 close to FETs

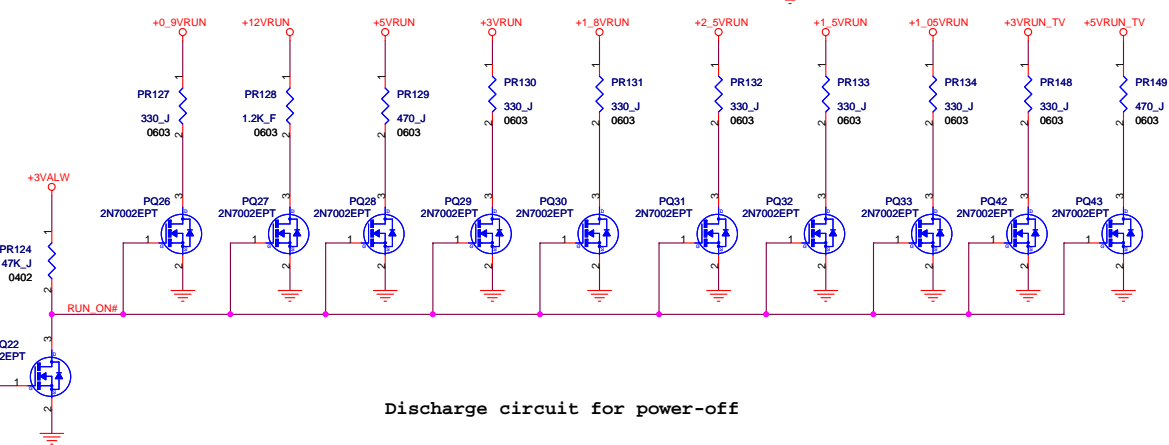
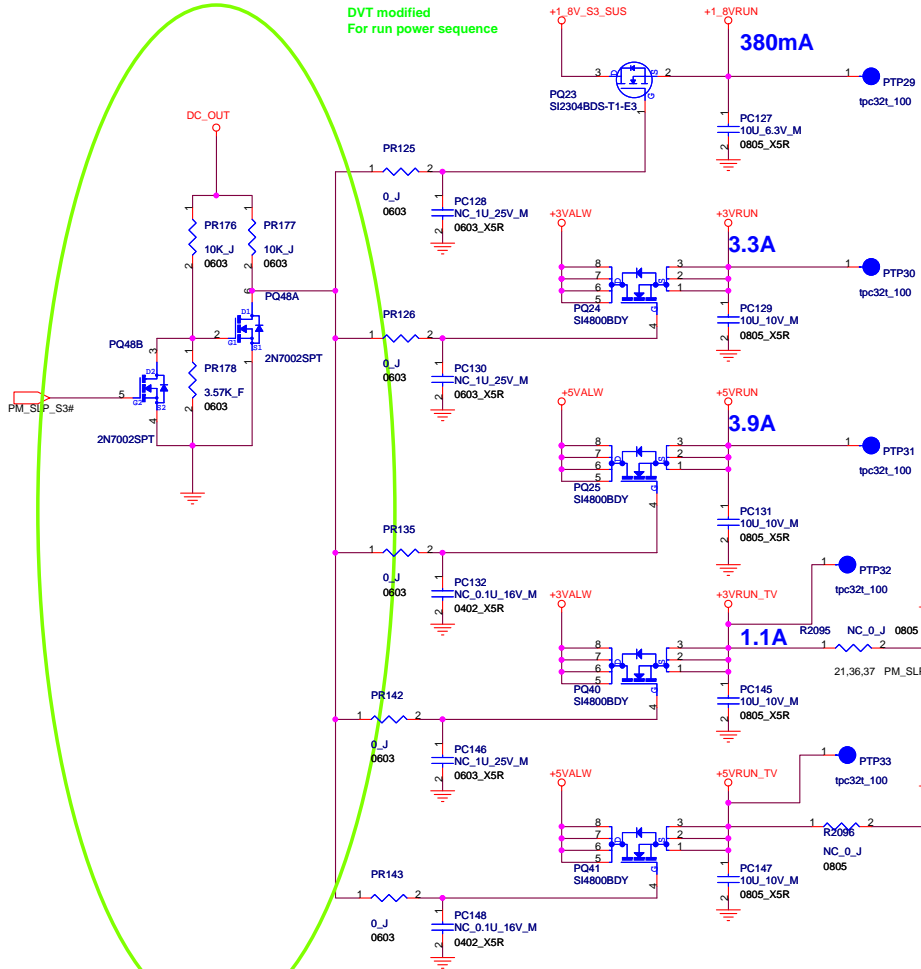
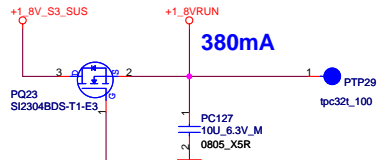
DVT modified
 Intersil request

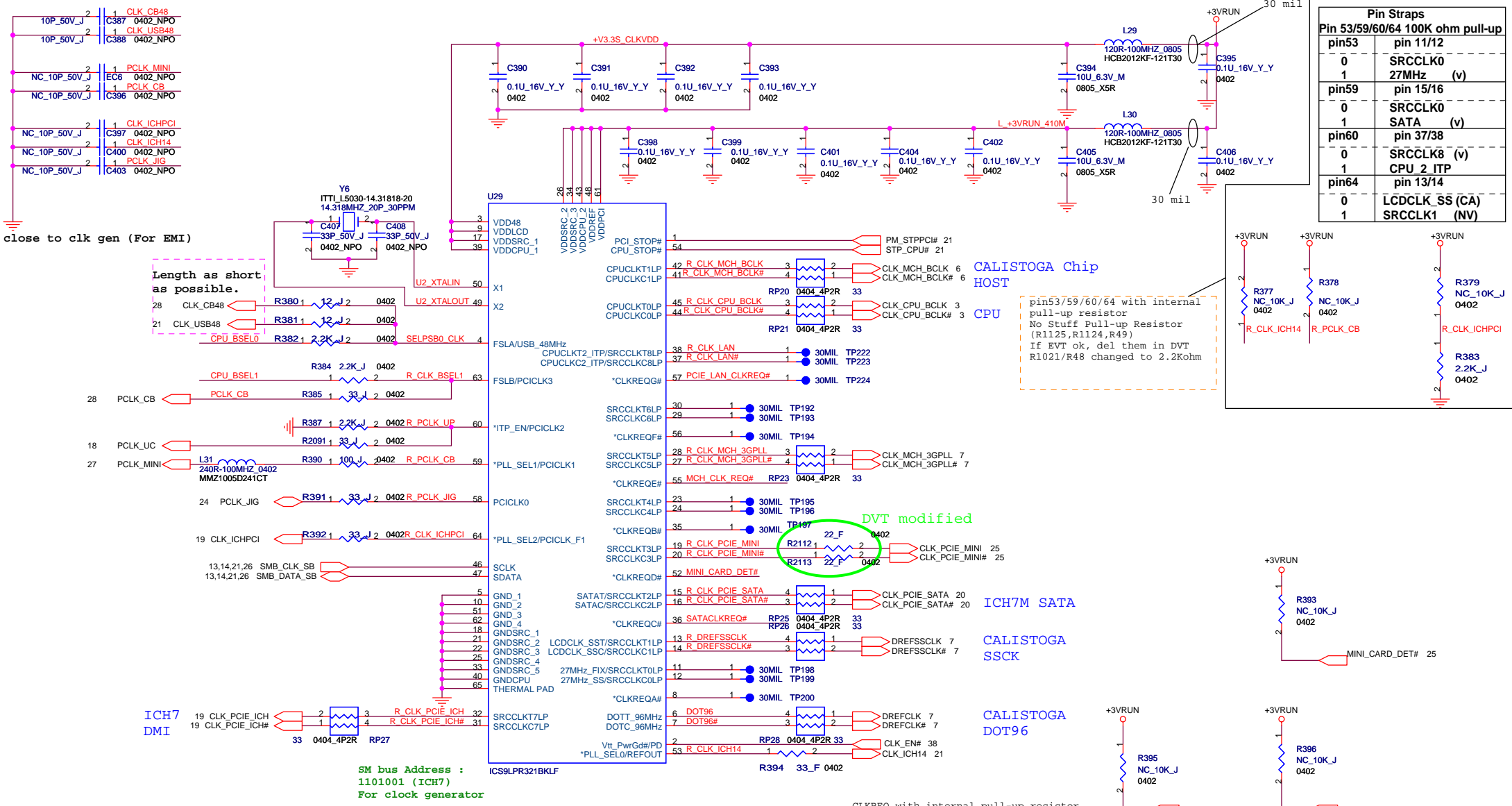
FOXCONN		HON HAI PRECISION IND. CO., LTD.	
		CPBG - R&D Division	
Title VHCORE(ISL6262)			
Size	Document Number	Rev	
Custom	MS80-1-04	0.1	
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+1.5VRUN/+1.05VRUN TO PWROK >99ms

DVT modified For run power sequence





Pin Straps			
Pin 53/59/60/64 100K ohm pull-up			
pin53	pin 11/12		
0	SRCLK0		
1	27MHz (v)		
pin59	pin 15/16		
0	SRCLK0		
1	SATA (v)		
pin60	pin 37/38		
0	SRCLK8 (v)		
1	CPU 2 ITP		
pin64	pin 13/14		
0	LDCCLK SS (CA)		
1	SRCLK1 (NV)		

close to clk gen (For EMI)

Length as short as possible.

pin53/59/60/64 with internal pull-up resistor
No Stuff Pull-up Resistor (R1125, R1124, R49)
If EVT ok, del them in DVT
R1021/R48 changed to 2.2Kohm

DVT modified

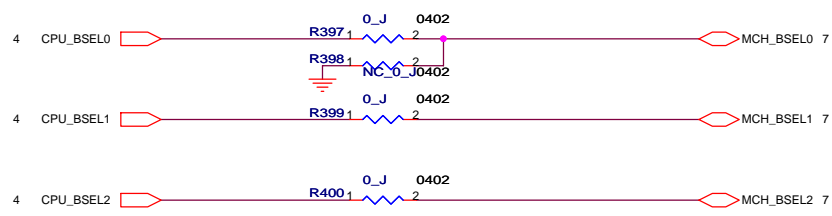
ICH7 DMI

SM bus Address : 1101001 (ICH7)
For clock generator

CLKREQ with internal pull-up resistor
No Stuff Pull-up Resistor (R69, R40, R41, R70, R1126, R1127)
If EVT ok, del them in DVT

FSB Frequency Table:

FSLB	FSLA	CPU	SRC[7:0]	PCI
0	0	100	100	33
0	1	133	100	33
1	0	200	100	33
1	1	166	100	33



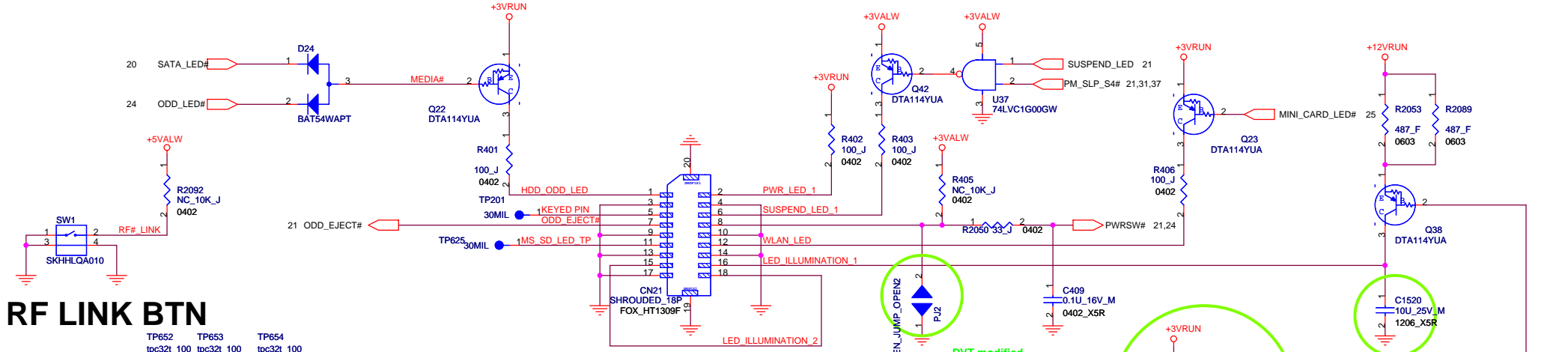
FOXCONN HON HAI PRECISION IND. CO., LTD.
CPBG - R&D Division

Title: **CLOCK GEN**

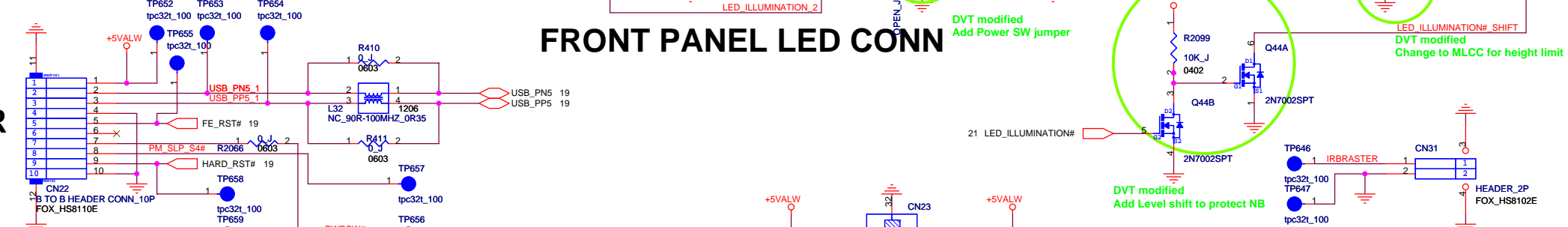
Size A3 Document Number: **MS80-1-04** Rev 0.1

Date: Tuesday, October 17, 2006 Sheet 41 of 44

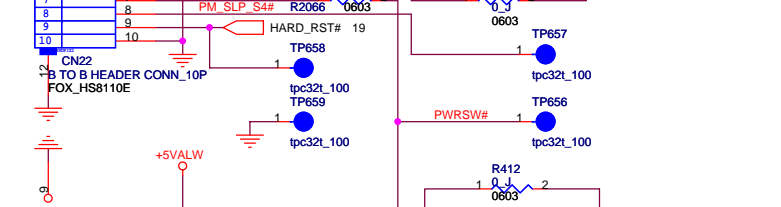
RF LINK BTN



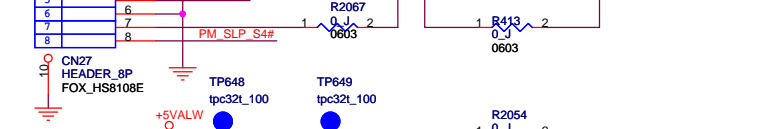
FRONT PANEL LED CONN



IR



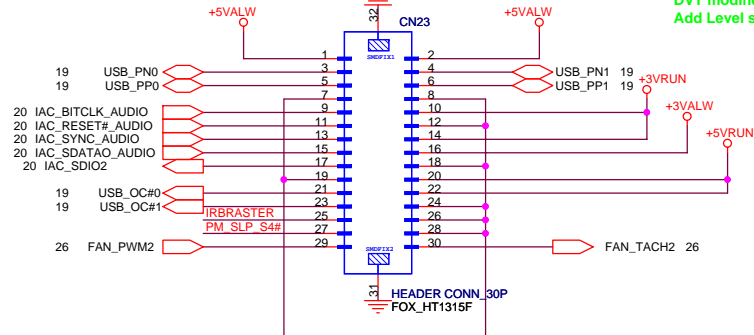
RF



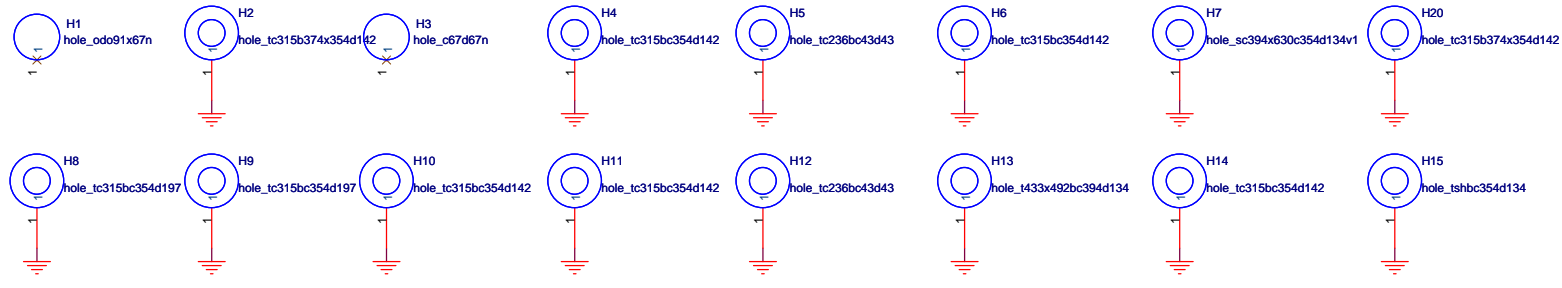
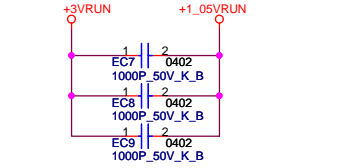
CEC



REAR IO BD CONN



IRBRASTER



FOXCONN HON HAI PRECISION IND. CO., LTD.
 R&D Division
 Title: **IR/RF/LED/HOLE**
 Size A3 Document Number: **MS80-1-04** Rev 0.1
 Date: Tuesday, October 17, 2006 Sheet 42 of 44

HISTORY
REV.: 0.10 (2006/07/18)

0718
P19,P21 change ODD_EJECT# from GPIO5 to GPIO10
P21 change SUSPEND_LED# from GPIO8 to GPIO25
P21 delete GPIO9 SB_RST#
P19 add GPIO17 as DDR_ALERT#

change thermal policy
P34,P3 delete PR173,Q35A,Q35B,PR171,PR172 and connect OVT_HM# to VR_TT# by adding R2087
P26,P21 add R2088,Q41,U41,CL1516 and HM_SHUTDOWN_CTL(GPIO26) for thermal policy

P27 add R287,R288,R289 for TV_GND

0719
P13-15 swap DDR signals for layout]
P42 change R2052,R2053,R2082,R2083 from 0ohm to 150 ohm
P42 connect CN22,CN27 pin4 to FM_SLP_S4# for anykey wake up in S3
P42 update H4,H5,H7,H10,H11,H15 for ME
P42 change R401,R407,R406 to 100ohm
P39 change PC132,PC148 to 0.1u.16v
P39 change PR148 to 330ohm
P21 change SUSPEND_LED from GPIO 25 to GPIO27
P42 add Q42 and change U37 to 74LVLC1G00GW for SUSPEND_LED

0720
P42 delete R2052,R2082,R2083,Q40 ;add CAP16 for ILLUMINATION_LED
P38 reserve PC177 for VHOCORE
P31 change F3 to PTTT SMD1206F110TF
P26 change D19 from IN1418 to CHS500H-40PT for VF

0721
Vendor review
P17 (1)delete D21,D22,R2018 and short,change Q31 to UPA672 for avoid capacitance effect 500pf for DDC bus
(2)NC U5,U38,U39 pin3 for capacitance concern
(3)change R110,R115,R120,R122 to 390 ohm
P18 (1)R2023 changed from 1K to 3K
(2)Q33A,Q33B changed from 2n7002 to UPA672T for capacitance concern

BOM modify for common parts
P26 U41 change to 74AHCI1G08GW.125
P21 change Q25 to MMBT3904(SECOS)
P26 change Q28,Q39 to MMBT3904(SECOS)
P35 change PQ47 to MMBT3904(SECOS)
P40 cahnge PC139 to 3300P YAGEO
P39 change R2034 to 10M_J TA-I
P21 change R1956 to 2.2k_J 0402
P17 R2007,R2008 change to 27K_F 0603
P17 R104,R105 change to 1.82k_F 0402
P3 change R2 to 150_F
P3 update R1
P15 update R77,R78,R79,R80
P20 update R163,R161

P37 delete FR79 for duplicate with GP4
P42 change R2053 to 931_F and add R2089 for power rating
P6-12 change U2 to 12-0Q82945-A300

0724
P41,P18 add R2090,R2091 for 33M clk input of microp from clk gen path
P40 dummy PC134,PC143 by power team
P42 swap L38,L32,L33(mirror vertical) for Layout
P35 change PLL1 to 4.7U-100KHZ_5.5A_0.04R(CYNTEC)
P28 change U20A pinJ2 to High active
P42 MS/SD LED move to FIO BOARD, CN21 pin 11 change to test pad
P25 connect WLAN_SW# to CN11 pin20
P18 connect P1.3 to INT0# by customer from vendor suggestion
P26 change CN13(fan) define to pin1-4 +SVRUN,TACH,GND,PWM by thermal team9(compatible with old models)

0725
P35 change PD19,PD20 to SSM34APT and dummy PD20 by power team
P24 update CN17 symbol and vendor P/N
P42 add SWL,R2092 for RF LINK BUTTON
P21 GPIO30 connect to HARD_RST#,GPIO 31 connect to FE_RST#

0726
P17 add CL1517,D21 by vendor suggestion
P19 GPIO29 connect to WLAN_SW# for TE
P42 mount CN28

0727
P21 GPIO7 connect to OVT_HM#,NC R2076 for OS shutdown
P38 dummy PC111,mountPC177 by power team
P37 change PC78,PC79 to 560U_2.5V_M (lower hight parts) for layout
P35 change PC169,PC171 to 330U_6.3V_M (NEC) (lower height) for layout
P36 Add PC181 for power ripple noise (for dip caps)
P38 Add PC183,PC184,PC185 for power ripple noise (for dip caps)
P40 add PC186 for power ripple noise (for dip caps)

0728
P38 change PC108 to 0.22u_16V_K 0603 size by power team
P35 change PC155,PC159,PC160 to 330U_6.3V_M ,SMD by power team(semtech)
P37 change PC78,PC70 to 330U_2.5V_M by power team(semtech)
P36 change PQ12 to IRF7904(PQ12A),change PQ14 to IRF7904(PQ12B)

0731
wlan power ldo
(1)add CL1518,CL1519,U42,by customer request for Intel module susceptibility to ripple noise
(2)MINI_PCIE+_3_3V change to +3VRUN source wlan led
P25 add Q43,R2093 by customer for avoid LED_WLAN# abnormal behavior from wlan module
P35 remove PC160 by power team

0801
P35 add PC191 by power team(vendor suggestion)
P36 NC PR50 by power team
P38 add PC192 by power team
P35 change PR155 to 16K_F,change PR164 o 6.2K_F for ocp
P36 change PR59 to 110K_F ,PR60 to 68K_F for OCP
P42 add EC7,EC8,EC9 for cpu,nh clk cross moat
P39 add R2095,R2096 for cost down
P25 (1)add R2094 for cost down,
(2)add R2097 by customer request
P17 change R2008 to 100K_J by customer

0803
P18 add R2098 by vendor suggestion
P42 change H13,H14 by ME

0804
P17 change CN29 to HS8102 cause of HS6102 not available

0816
P40 change PR140 from 140K to 143K to increase +12V voltage
P38 change PR119,PR120 from NC to 10ohm for interail request
P30 change R320,R2081 from NC to 10K,change R318 from 1M to 100K for MOR request to avoid SD/MS issue
P34 change PR2 from 1K to 20K,change PR8 from 4.7K to 1K to change OVP point
P35 change PR155 from 16K to 11K for adjusting OCP point
P36 change PR59 from 110K to 100K,change PR65 from 100K to 51K
PR60 from 68K to 110K for adjusting OCP point
P40 change PQ37 from SI4892DVT to SI4800BDY for OCP
P42 add Q44 for level shift of LED_ILLUMINATION#
P40 change PD16 from SSM34APT to NC for cost down
P36 change PD10,PD11 from SSM34APT to NC for cost down
P37 change PD13 from SSM54PT to NC for cost down
P35 change PD18 from SSM34APT to NC for cost down

0817
P24 CN7 Pin49,50->NC;Pin43,44->GND; for ODD can not detect issue
P18 R2090->NC,C200,C202,Y1->Mount; for HDMI no audio issue
P35 PQ44,PQ45 use 2nd source as main source for stock
P36 PQ13,PQ15 use 2nd source as main source for stock

0822
P35 PR169,PR170 change to NC to change SC411 work mode to continue mode
P34 PR2 20K->15K for OVP point change

0905
P42 Add PJ2(Power SW jumper for TE request
P19 Cancel BIOS socket(U31) and add BIOS chip
P28 PC18402 GRST# signal change to PC1RST# for can not program GUID issue
P36 Change 1.5V and 1.05V timing for power good glitch issue
P21,35 Add circuit to adjust PM_SMRST# timing
P26 Change HW monitor power to 3VALW

0918
P35 PC176 change from 0.1u to 0.01u for Mode change to continue
Add PR175(NC,0ohm) and PC193(0.01u) for mode change
Change PC157 to 22nF and NC PC191 for better performance
P37 Add PC88,PC89 for better power performance
P38 Change PR88,PC192 position base on datasheet
Change PR116,PC114 for CPU load line SPEC
Change PL7,PL8 for height limit
P39 Change enable circuit or run power sequence
P40 Change for +12V power sequence
P36 Change PC60,PC61, add PC147 for ripple and cost down
Change PC58,PC59 for cost down
ALL input 1210 MLCC(PC5,149,150,151,163,164,46,51,49,50,55,68,69,70,91,92,105,106,134,135,136) change to 1206 with 1210 pad

0919
P31 USB power switch changed for MOR request

0921
P42 Del CAP16 and Add CL1520 for height limit

0925
P19,21,24 Add X-BUS function on JIG connector

0926
PCN1,CN32,CN29,CN24,CN25,CN13,CN28,CN31,CN22 Add test point
P25 Modified WLAN connector and terminator type for mechanical
P16 CN3 change D-BUS conn color for ME requirement
P32 CN25 change RJ45 conn color for ME requirement
P24 CN32 change to HM4202E-DW for ME requirement

0927
P27 CN24 change to SCN5538G8TNW01AG for ME requirement

0928
H2, H7, H13, H15, H20 change screw hole footprint for ME requirement

1002
P37 PC88 pin2 and PC89 pin2 change connection to GND_SC486 in order to improve 1.8V unstable for power requirement.
P38 Remove PR182,PR183,PR184,PR185 to release layout space.
P41 Change CLK_PCIE_MINI damping resistor from 33ohm to 22ohm for signal quality improvement.

1004
P17 Modify for sill1390 and sill1392 co-design.
P18 Add R2138,R2139,R2140,R2141 to connect I2C bus for FAE recommended.
P39 U33 change to Schmitt trigger part for MOR requirement.
P40 Remove PR179,PR180,add 12V_EN for power requirement.
P40 Del MAX8546_DC net and connect DC_OUT for PUL0 VIN.

1005
P17 Modified Sill139X circuit
P21 Add D35 on PowerOK signal for ICH sequence timing

1009
P17 Modified Sill139X circuit
P34 Add PC196,197,198,199 for EMI
P38 Add PR182,PR183 PC194,PC195 for EMI

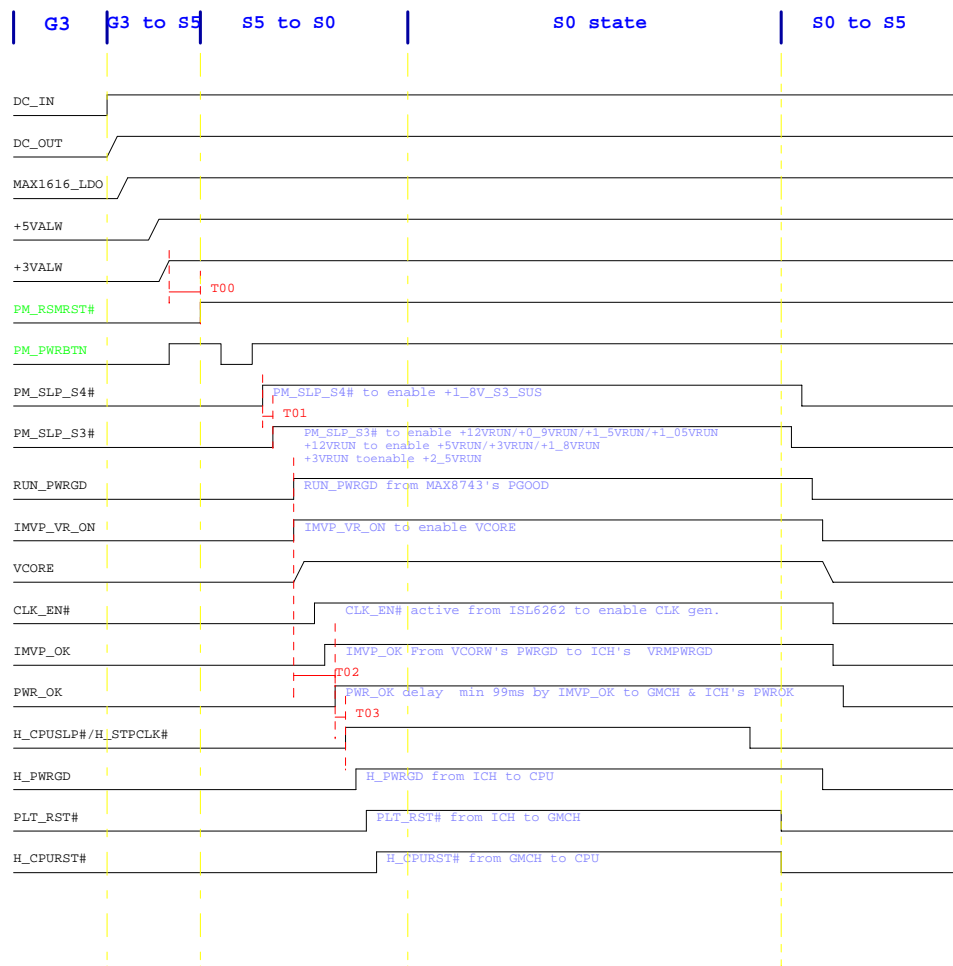
1010
P24 ODD CONN(CN7)change to FFC and pin swapped for ME
P30 Front IO board CONN(CN7)change type for ME request
C335,336,341,342 change to NC for MOR request

1011
P34 Change DC_IN test point size

1013
P16 CRT CONN(CN3) pin10 connect to GND according to SONY SPEC
P27 C412 change from 100p for MOR request
P30 R323 change to 100K for MOR request
P31 Remove USB power fuse for MOR request
P39 Add R2151 for PWR_OK sequence

MS80 Power On Sequence Timing

Version : 0.0
Modified date : 8/11/2006



- T00 : (Min 10ms) ALW power supply to PM_RSMRST# at least 10ms (Please refer to ICH7 EDS of t204 timing)
- T01 : (1 - 2 RTCCCLK) PM_SLP4# to PM_SLP3# (Please refer to ICH7 EDS of t234 timing)
- T02 : (Min 99ms) RUN_PWRGD to IMVP_OK (Please refer to ICH7 EDS of t214 timing)
- T03 : (Max 50ns) PWR_OK active to H_CPUSLP# and H_STPCLK#

Remark: (Item1,2,3 add Diode; Item4,5,6 add discharge circuit; Item7 for implement TV)
SPEC please refer to Intel 16981 15.4 GMCH/ICH7M Platform Power -up Requirements)

1. V5REF(+5VRUN) -> +3VRUN, dt:0.7mV
2. V5REF_SUS(+5VALW) -> +3VALW, dt:0.7mV
3. +2.5VRUN -> GMCH_VCC(1.05V), dt:0.7mV
4. +1.5VRUN -> +GMCH(1.05V), dt:0.7mV
5. +3.3VRUN -> +2.5VRUN, dt:0.3mV
6. +3.3VRUN -> +5VRUN (VccLAN), dt:0.3mV
7. +3.3VRUN -> +1.5VRUN(TV), dt:0.7mV

